

FIG. 1
RELATED ART

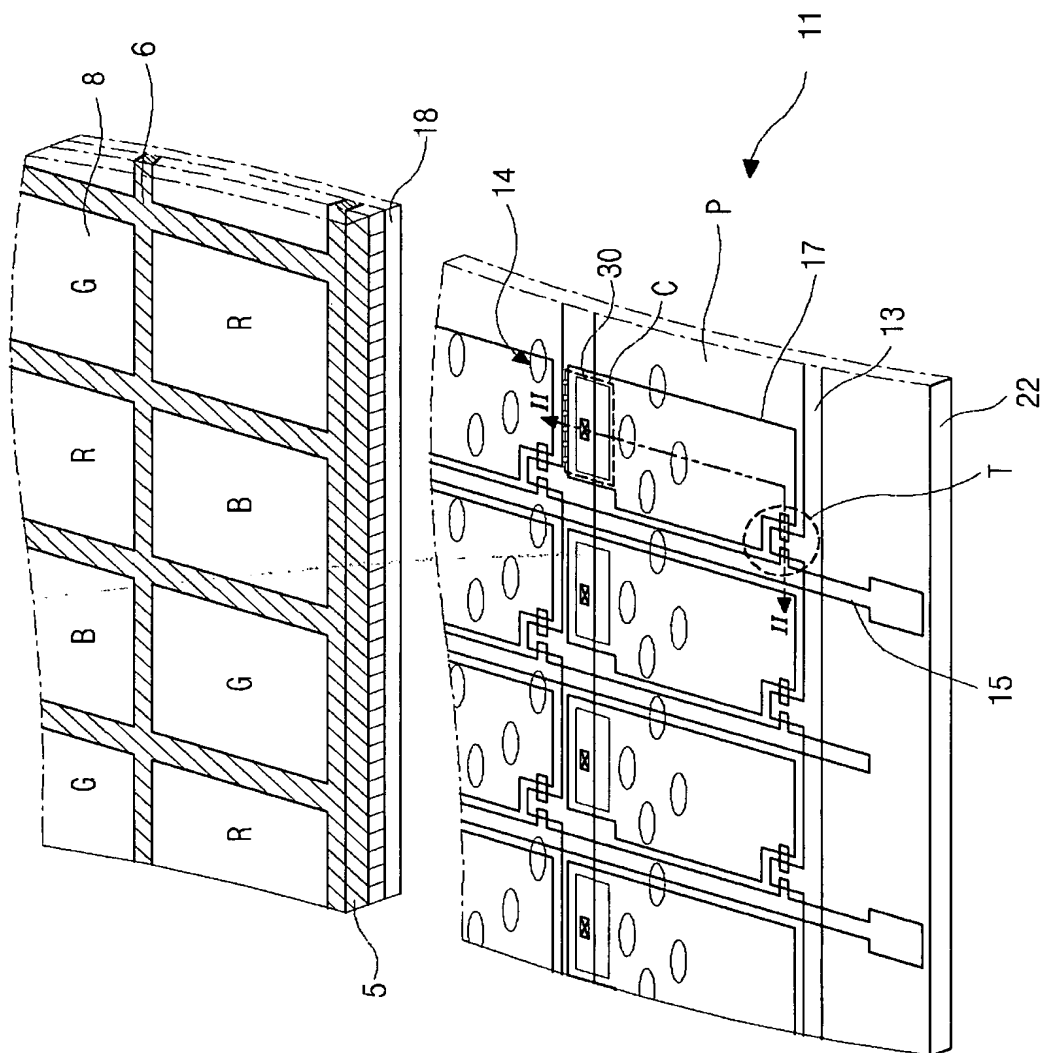


FIG. 2
RELATED ART

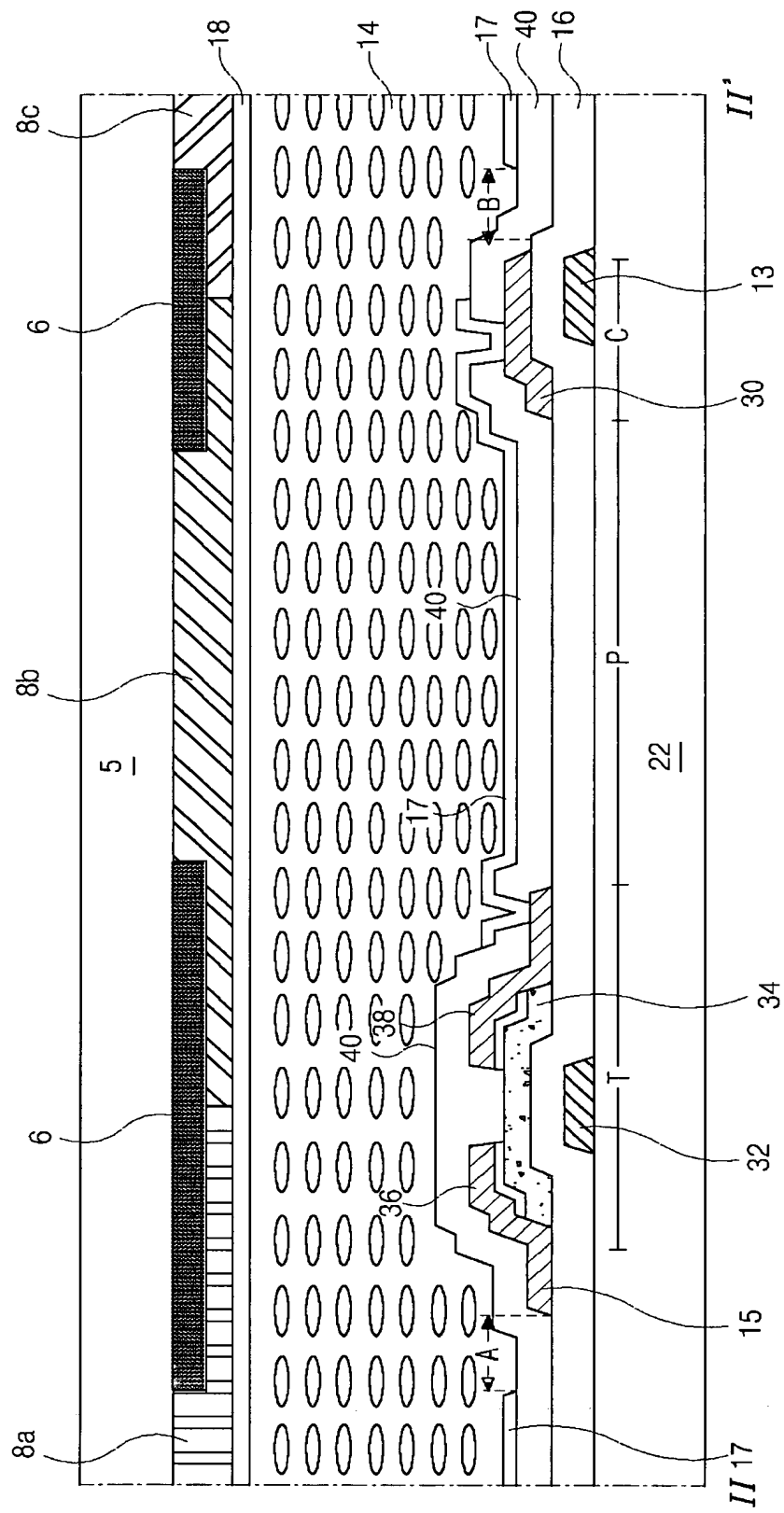


FIG. 3

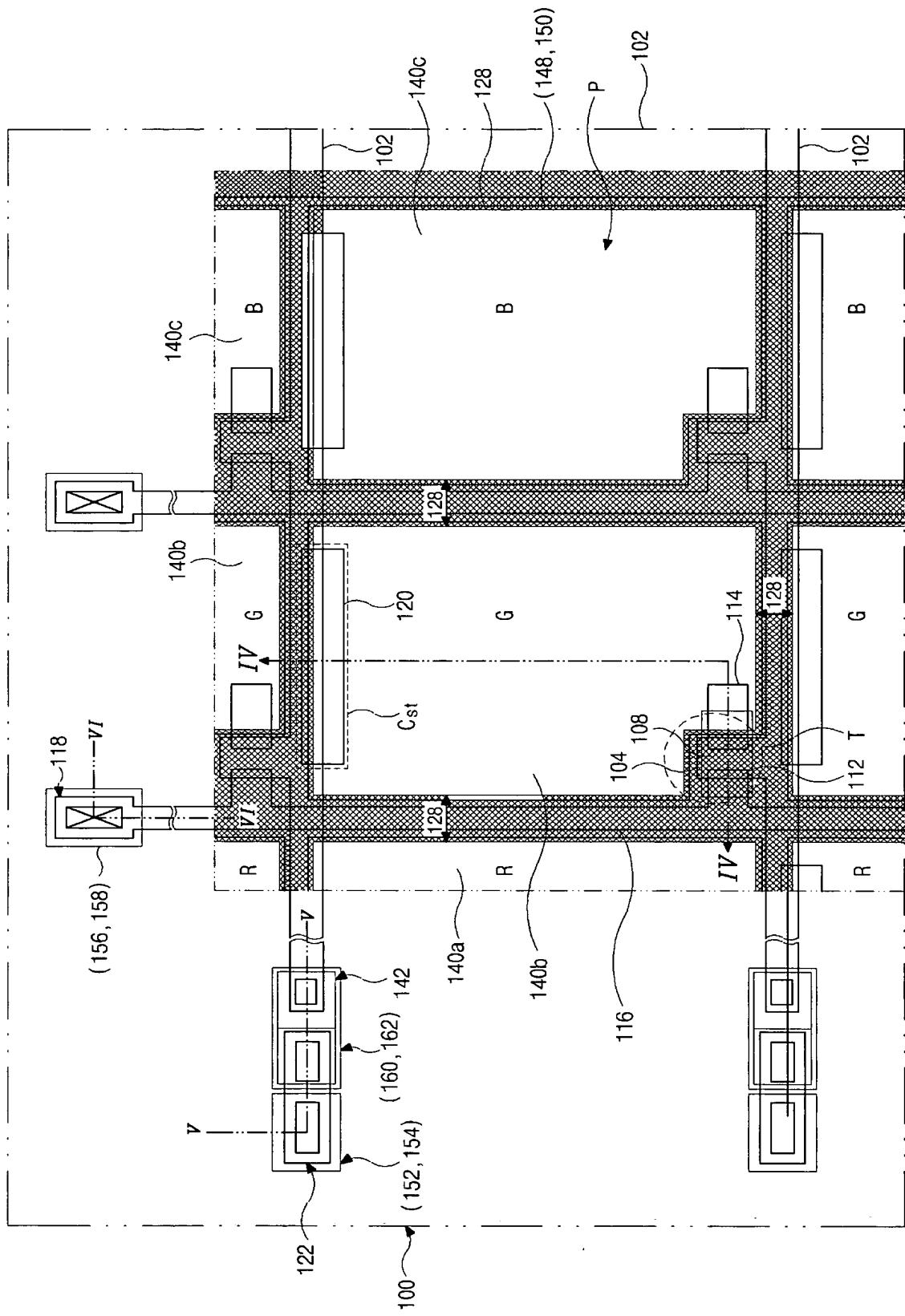


FIG. 4A

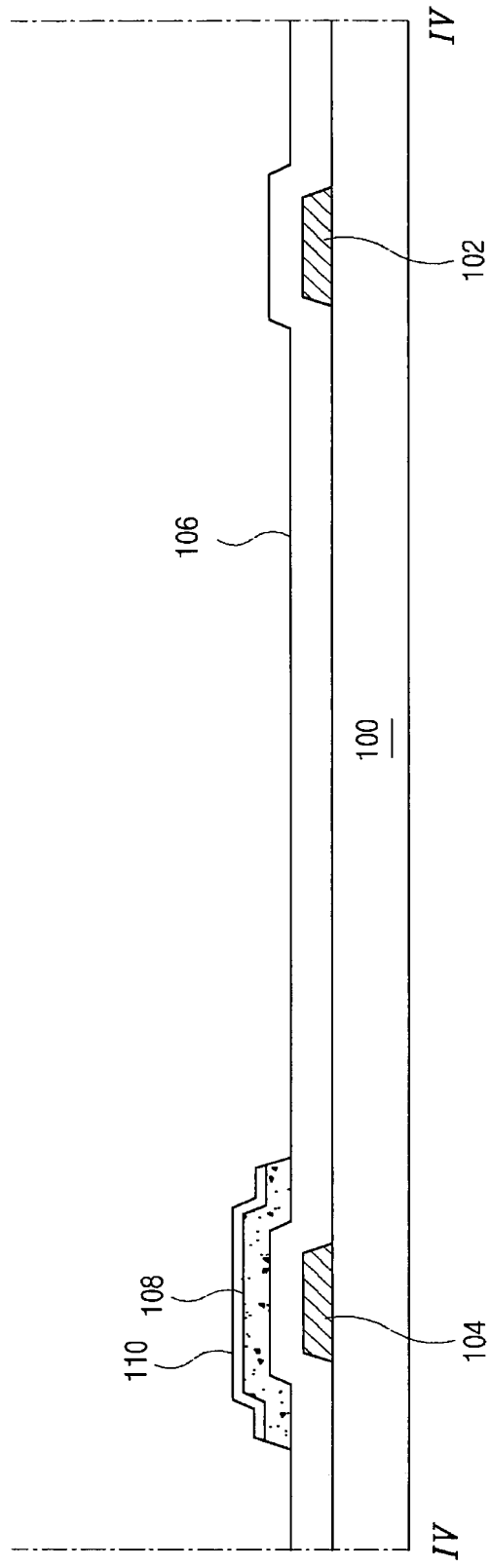


FIG. 4C

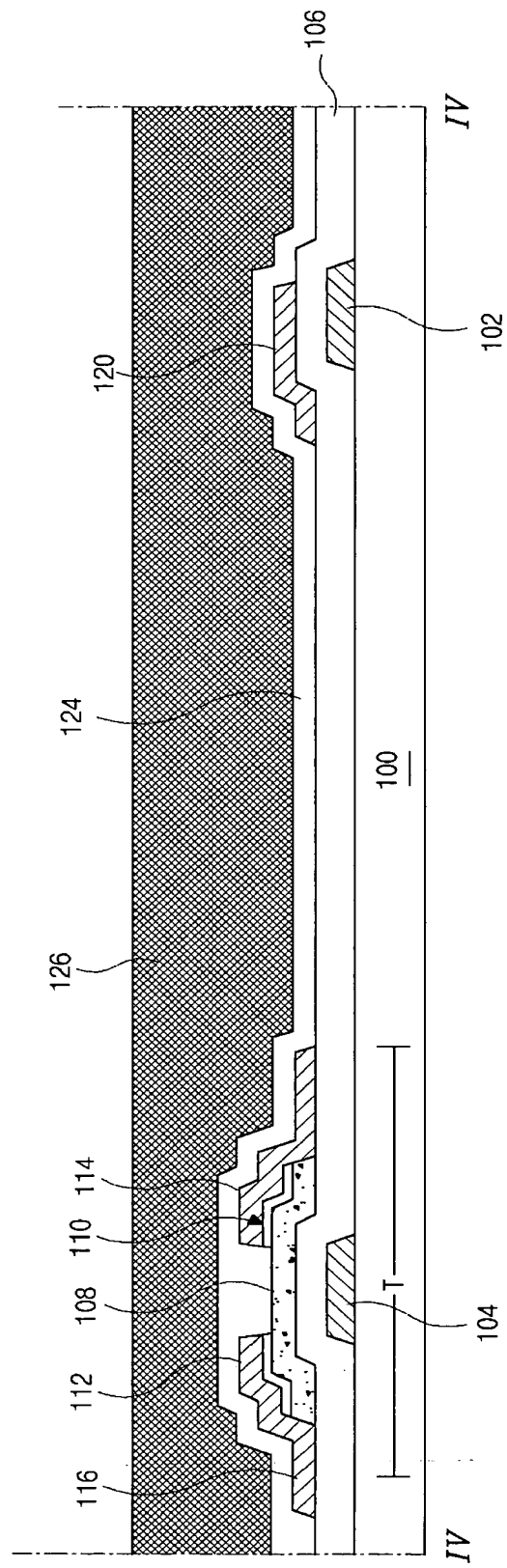


FIG. 4D

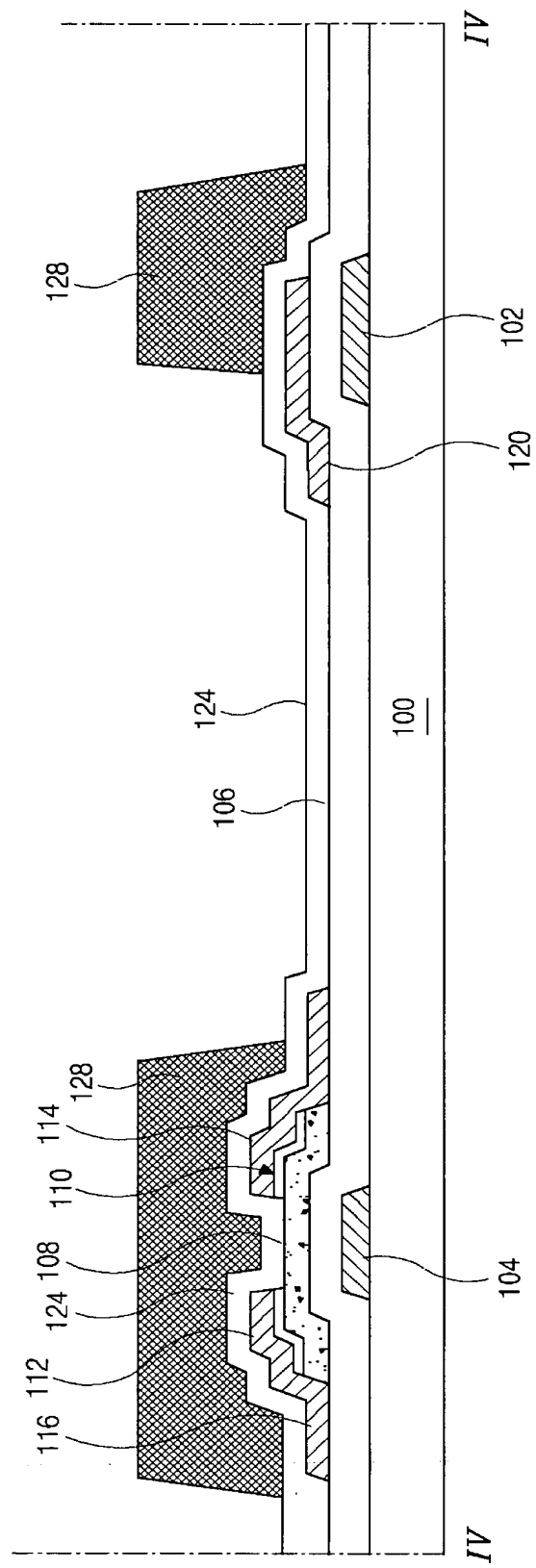


FIG. 4E

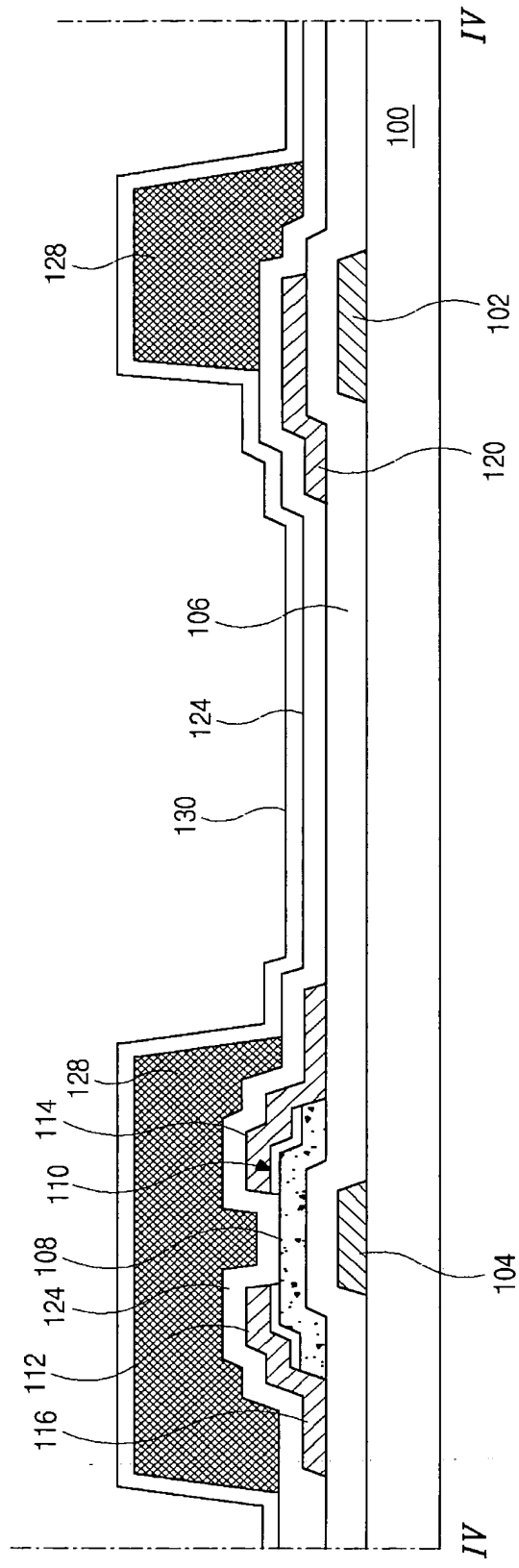


FIG. 4F

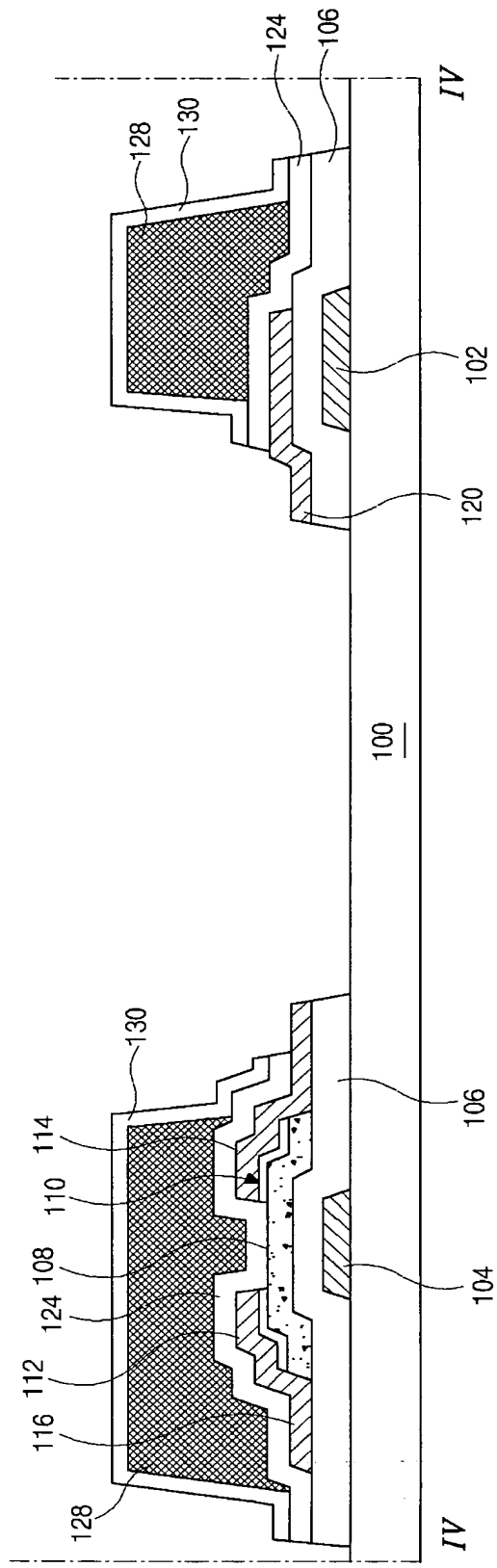


FIG. 4G

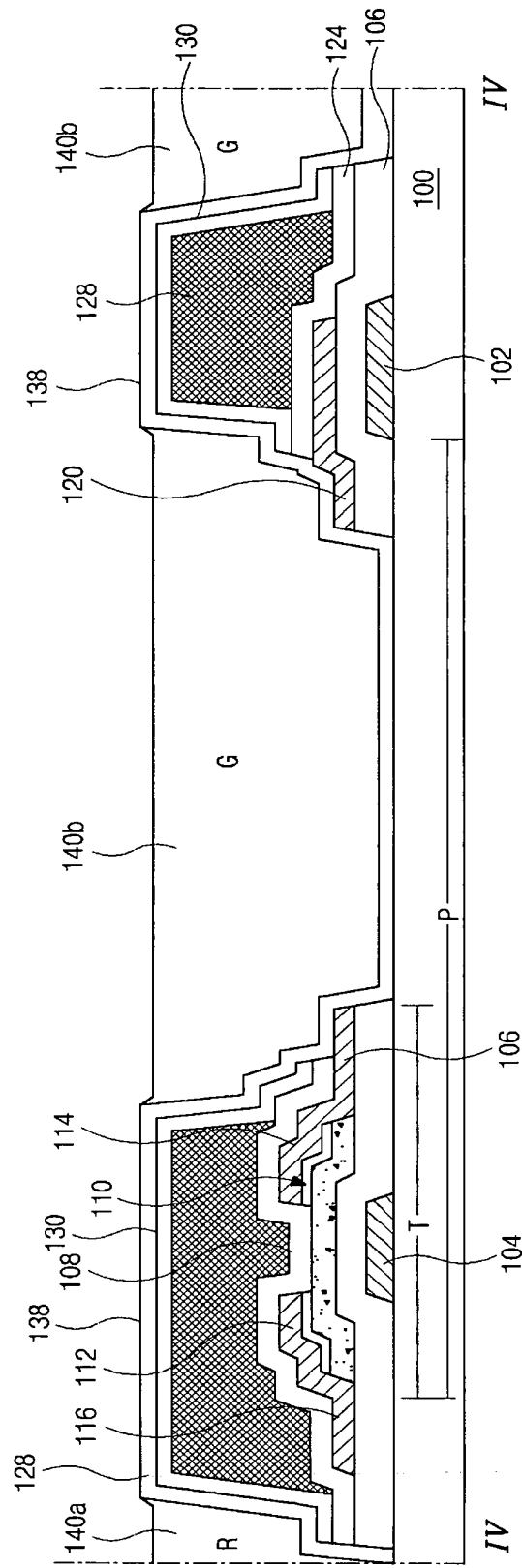


FIG. 4H

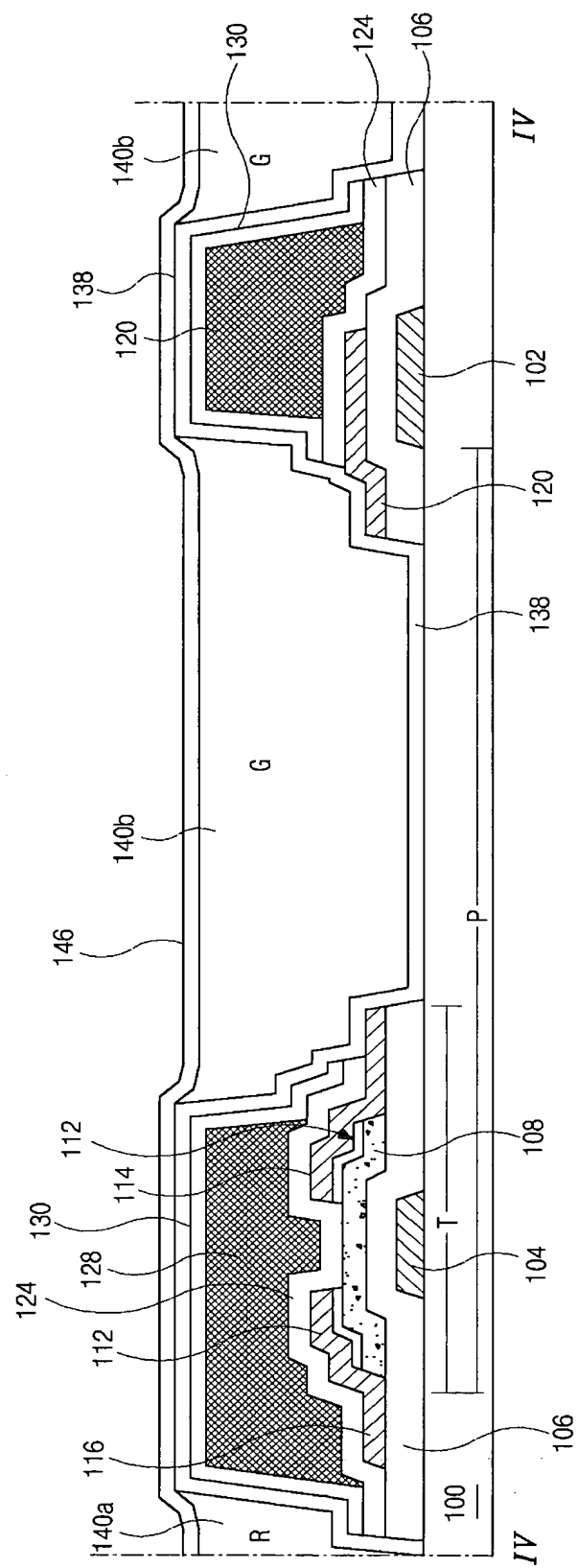


FIG. 4I

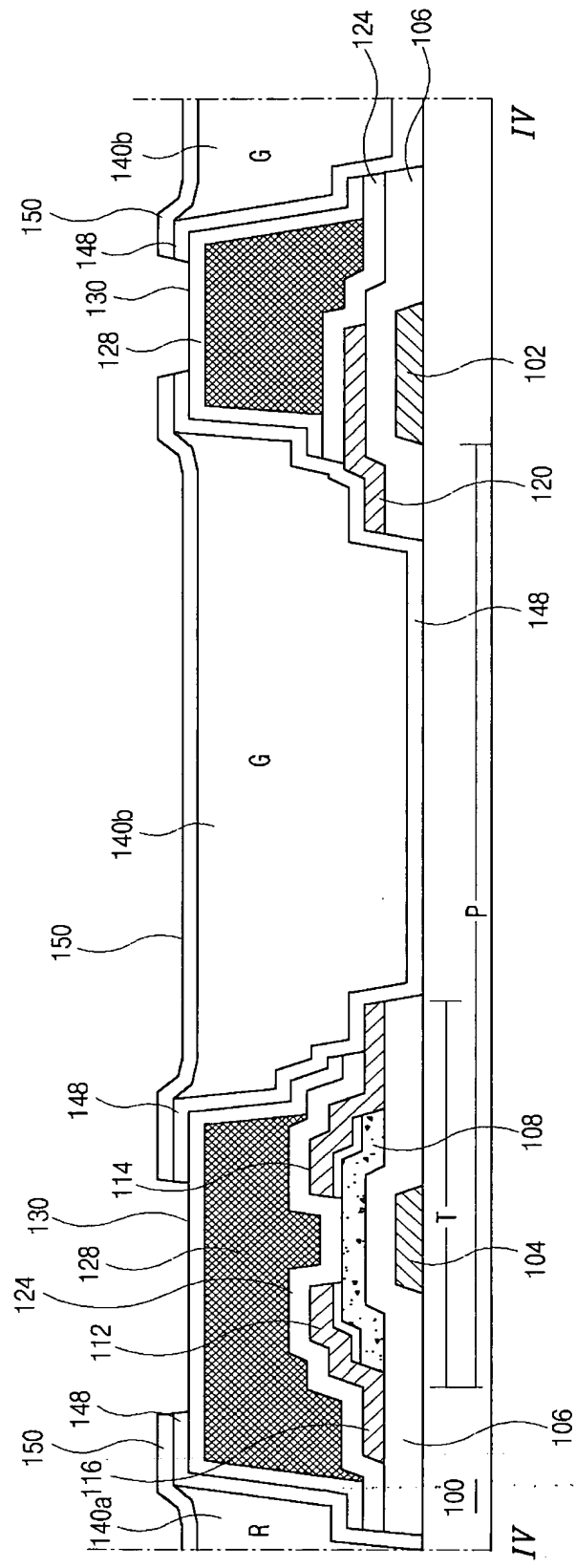


FIG. 5A

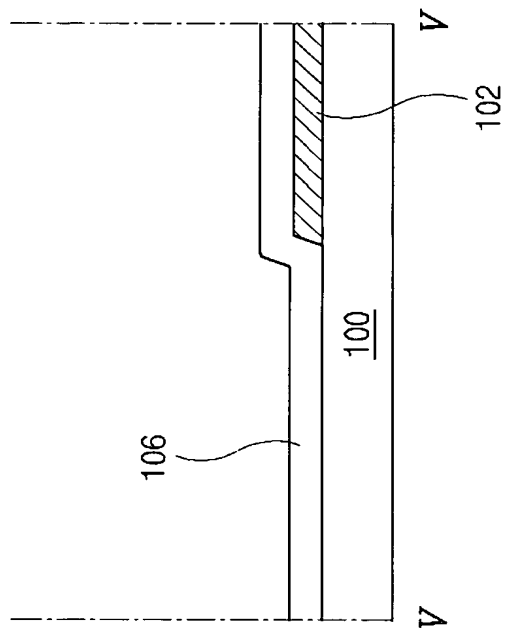


FIG. 5B

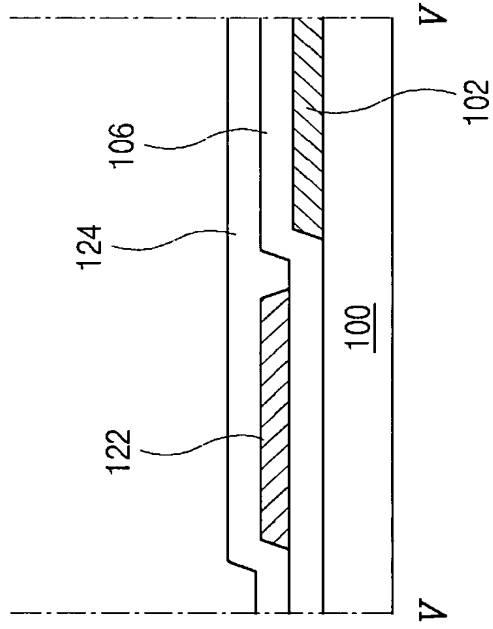


FIG. 5C

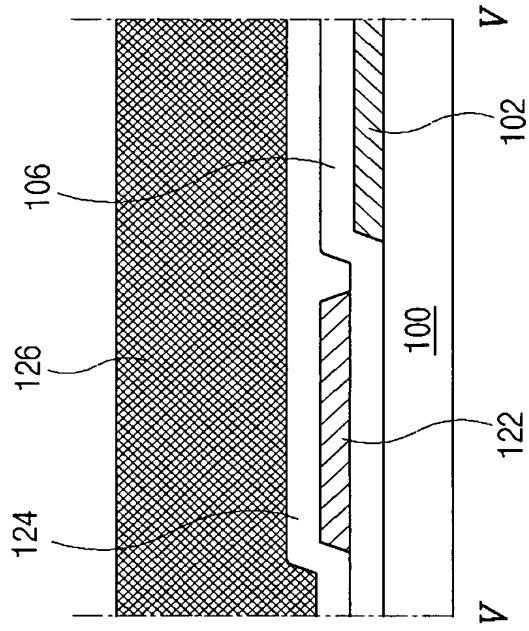


FIG. 5D

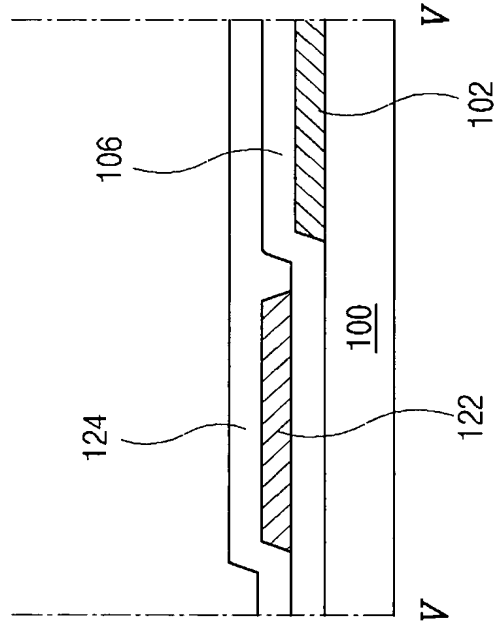


FIG. 5E

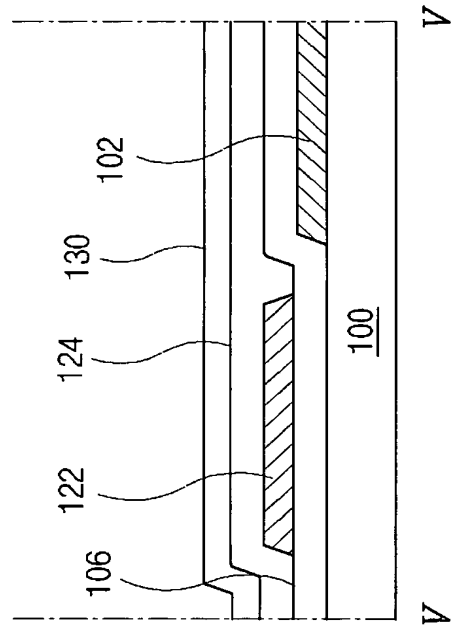


FIG. 5F

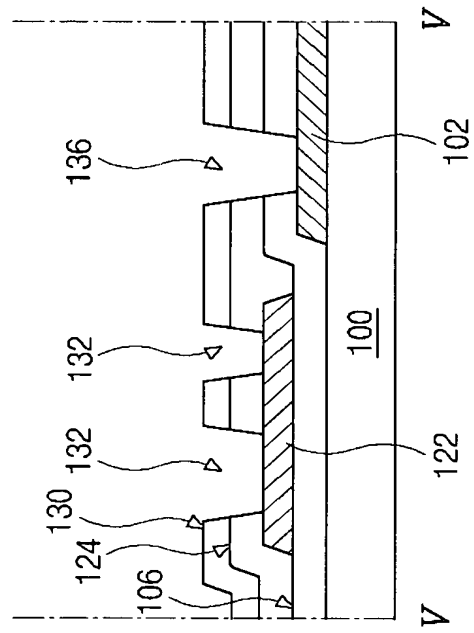


FIG. 5H

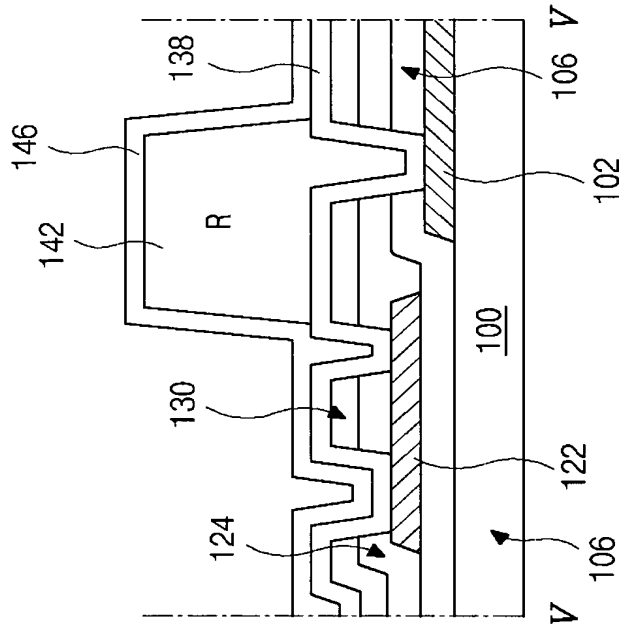


FIG. 51

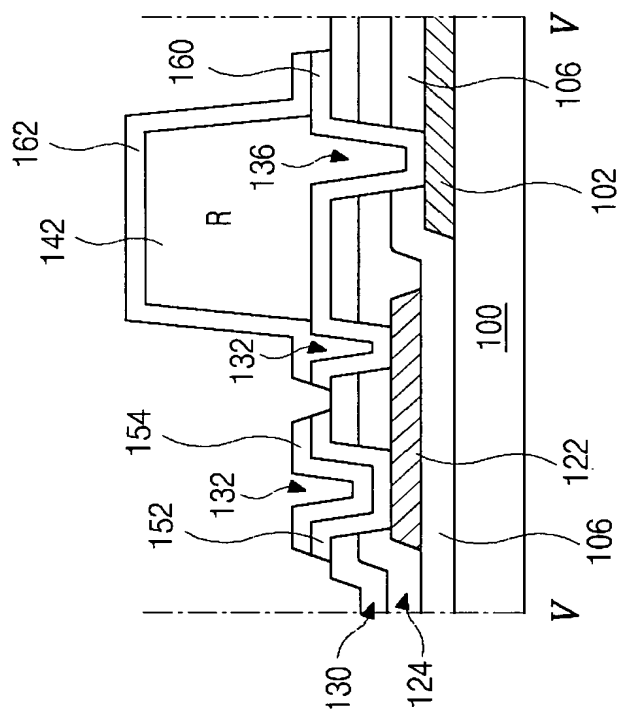


FIG. 6A

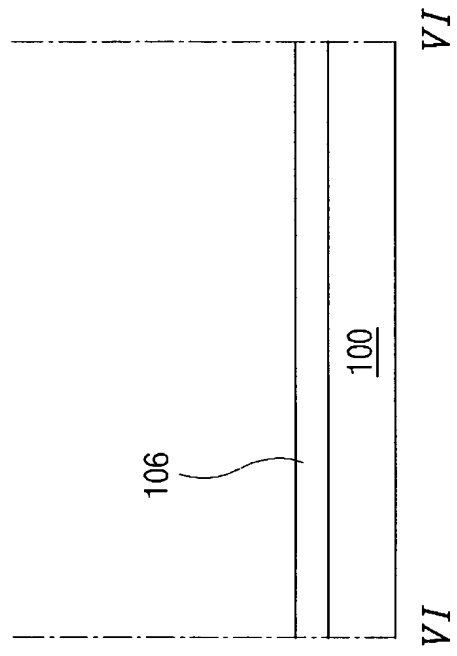


FIG. 6B

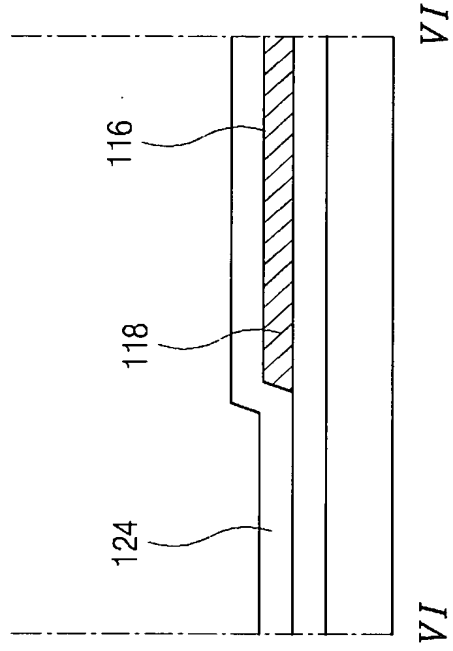


FIG. 6C

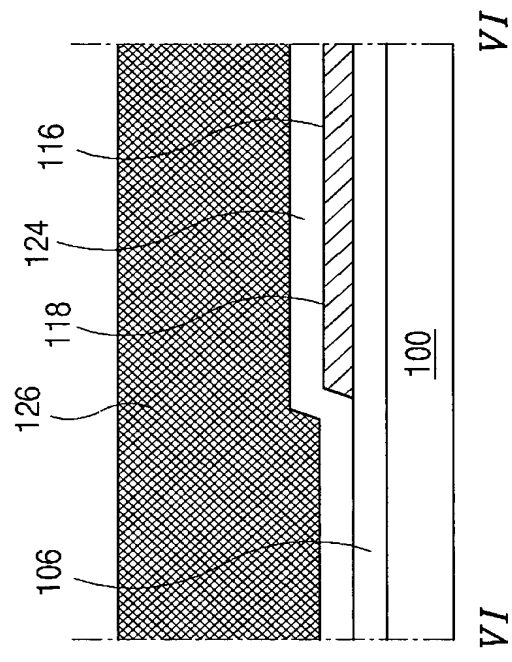


FIG. 6D

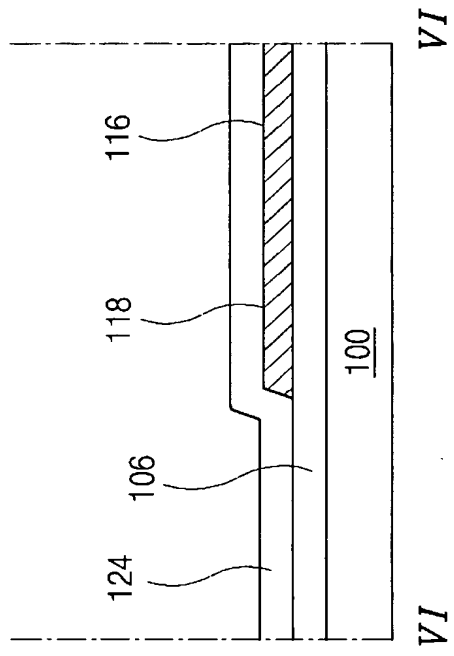


FIG. 6E

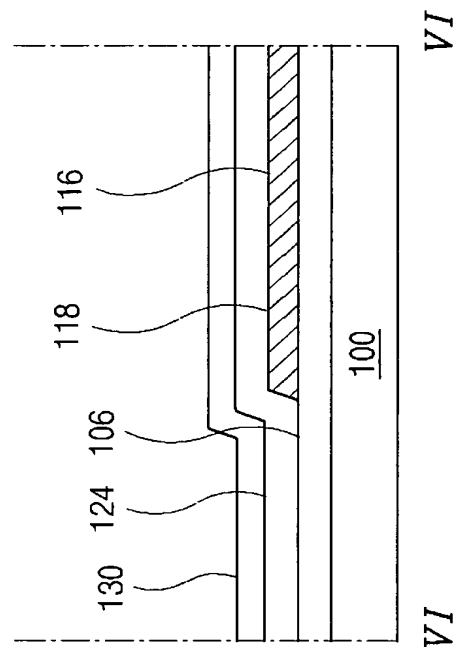


FIG. 6F

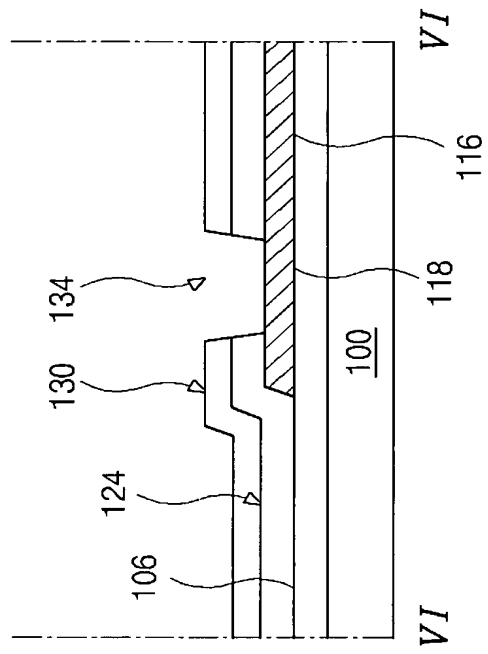


FIG. 6G

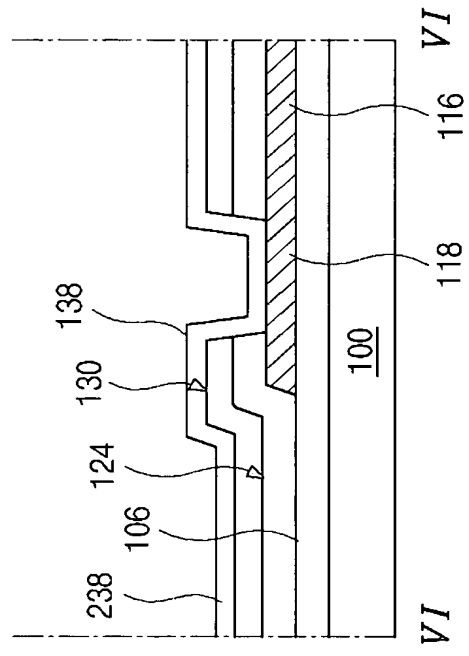


FIG. 6H

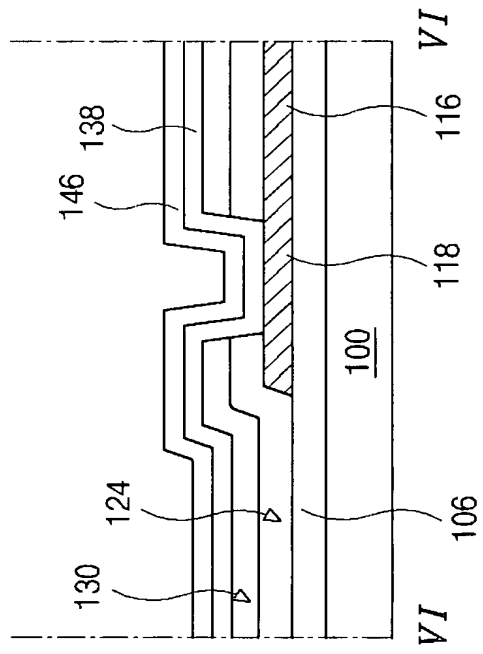
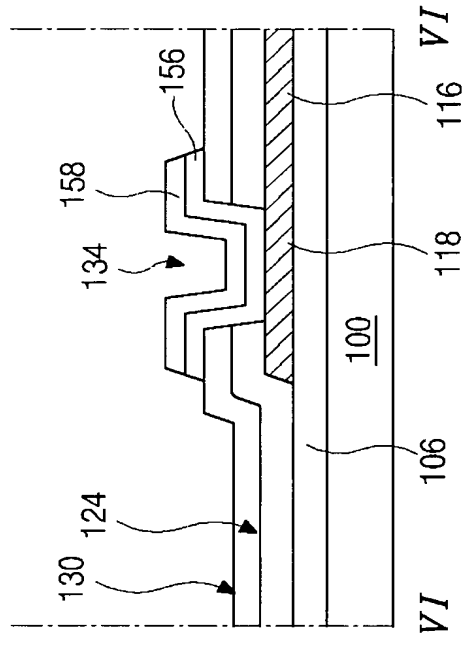


FIG. 6I



This diagram shows a cross-section of a semiconductor device. It features a substrate 200 with various layers and structures. On the left, there are two rectangular regions labeled 230, each containing a smaller rectangle with an 'X' inside, representing a contact or pad. These are connected by a layer 266b. Below them is a larger rectangular region 232, which contains several smaller rectangles, some labeled 240a (284, 286) and others 276, 278. A dashed line IX passes through this region. To the right of the substrate, there is a complex stack of layers. A thick, hatched layer 266c covers most of the top surface. Within this hatched area, there are several rectangular openings or recesses. One such opening is labeled 236a and contains a small square feature 248. Another opening is labeled 238a and contains a small square feature 228. A dashed line G passes through these openings. The entire structure is bounded by vertical walls 224 and 234a. At the bottom, there are more rectangular regions labeled 266a and 266b. A dashed line VIII passes through one of these regions. Various other labels like 202, 254, 256, 266c, and (272, 274) indicate specific dimensions or features.

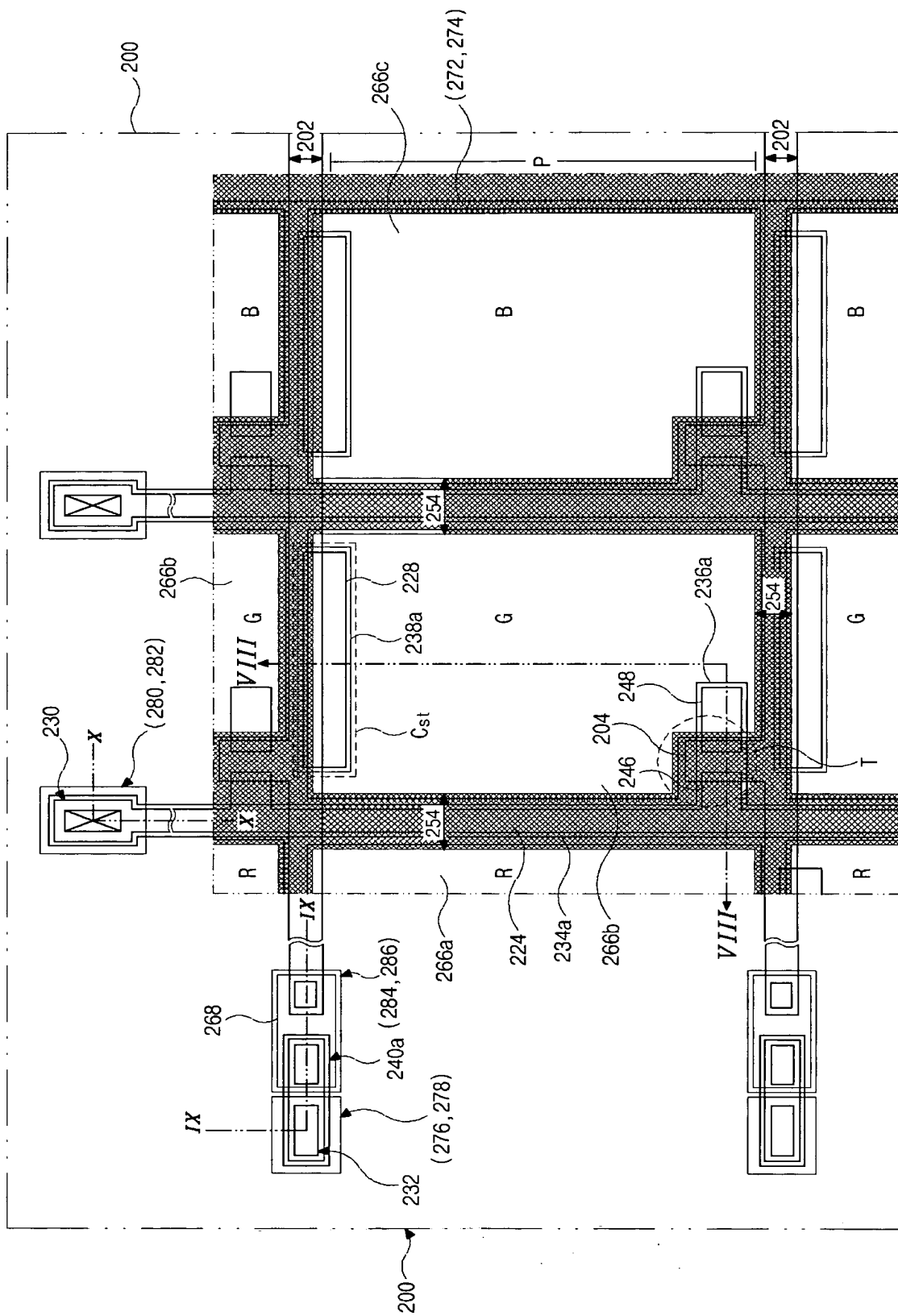


FIG. 8A

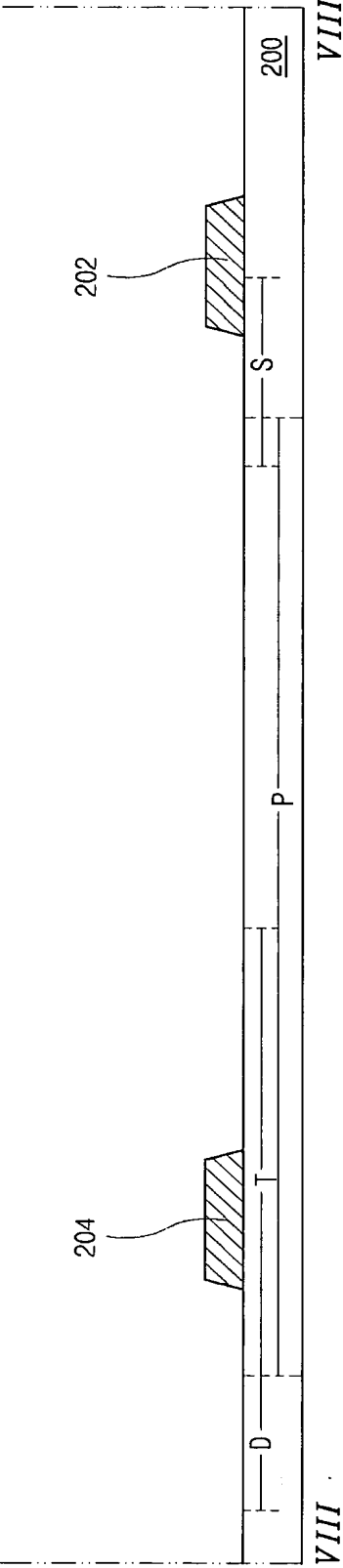


FIG. 8B

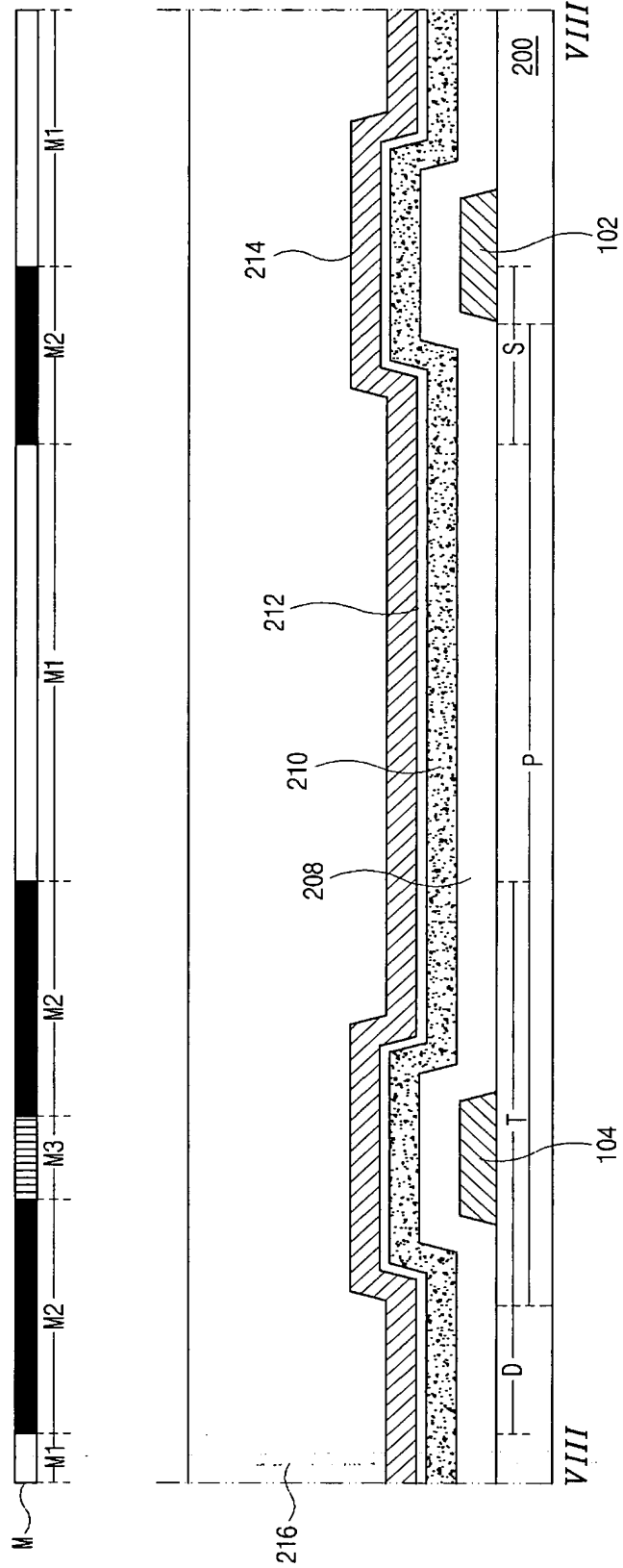


FIG. 8

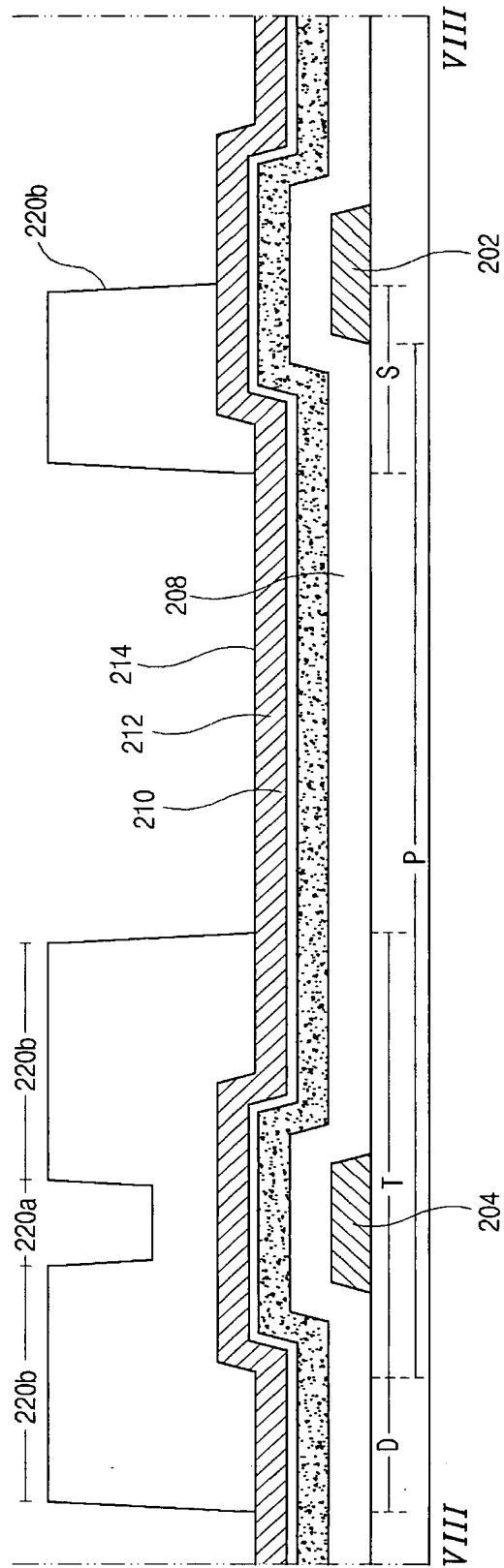


FIG. 8D

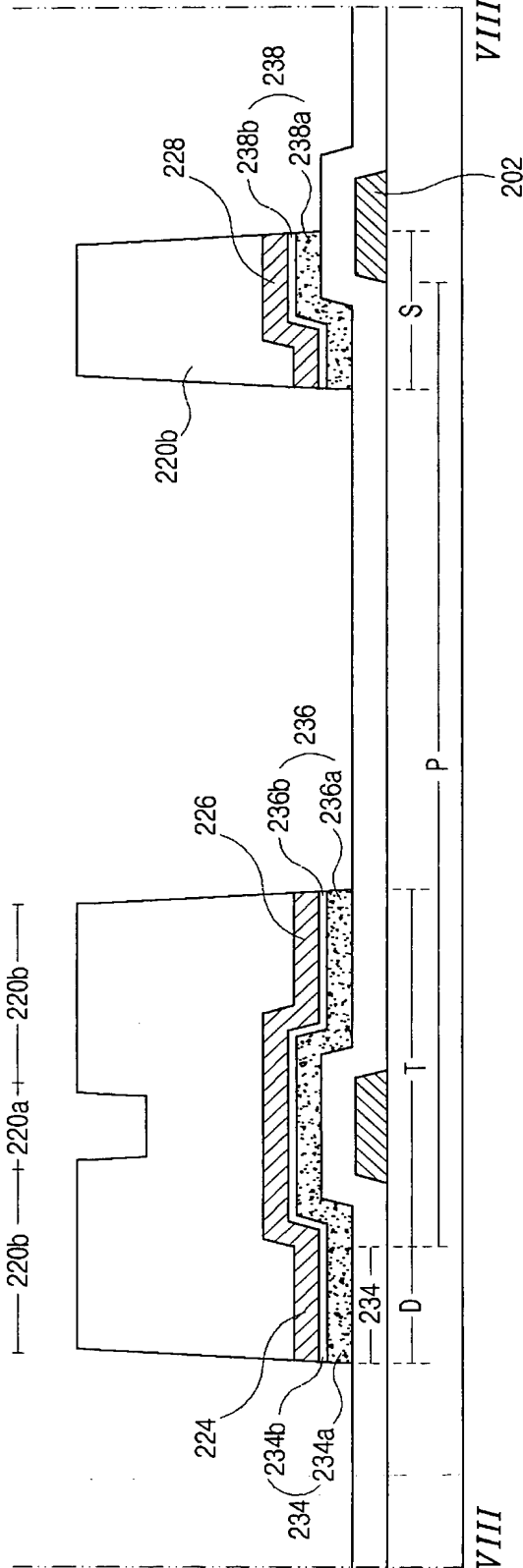


FIG. 8E

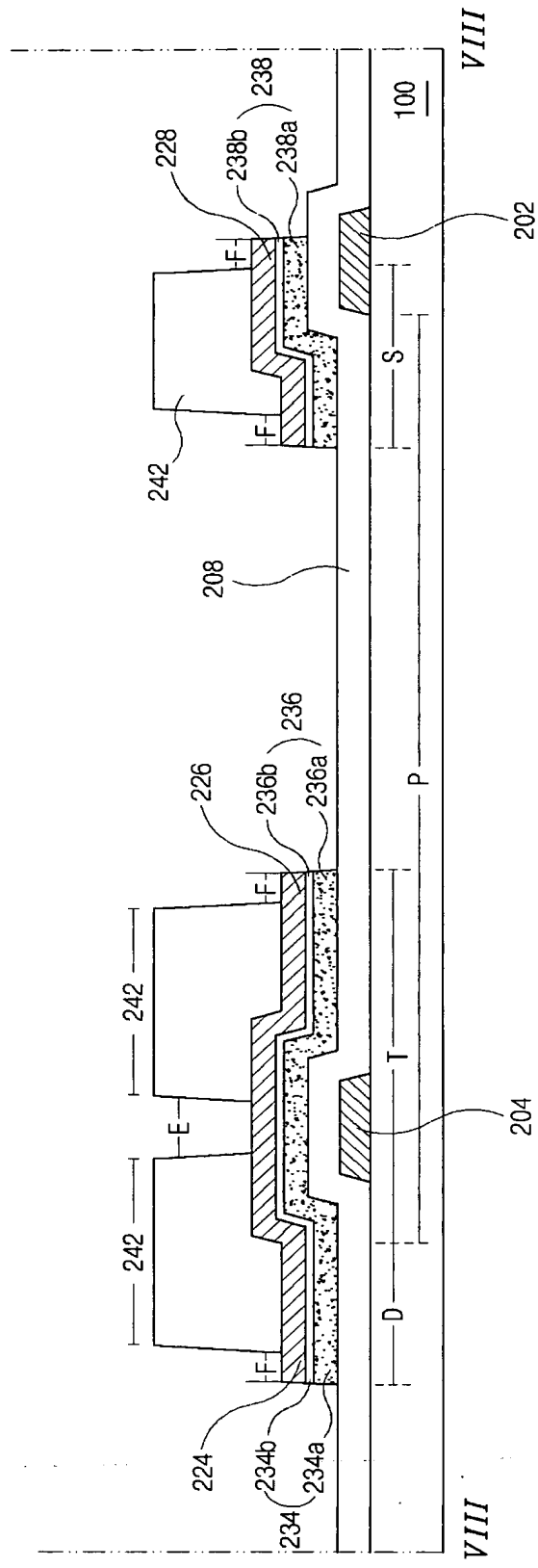


FIG. 8F

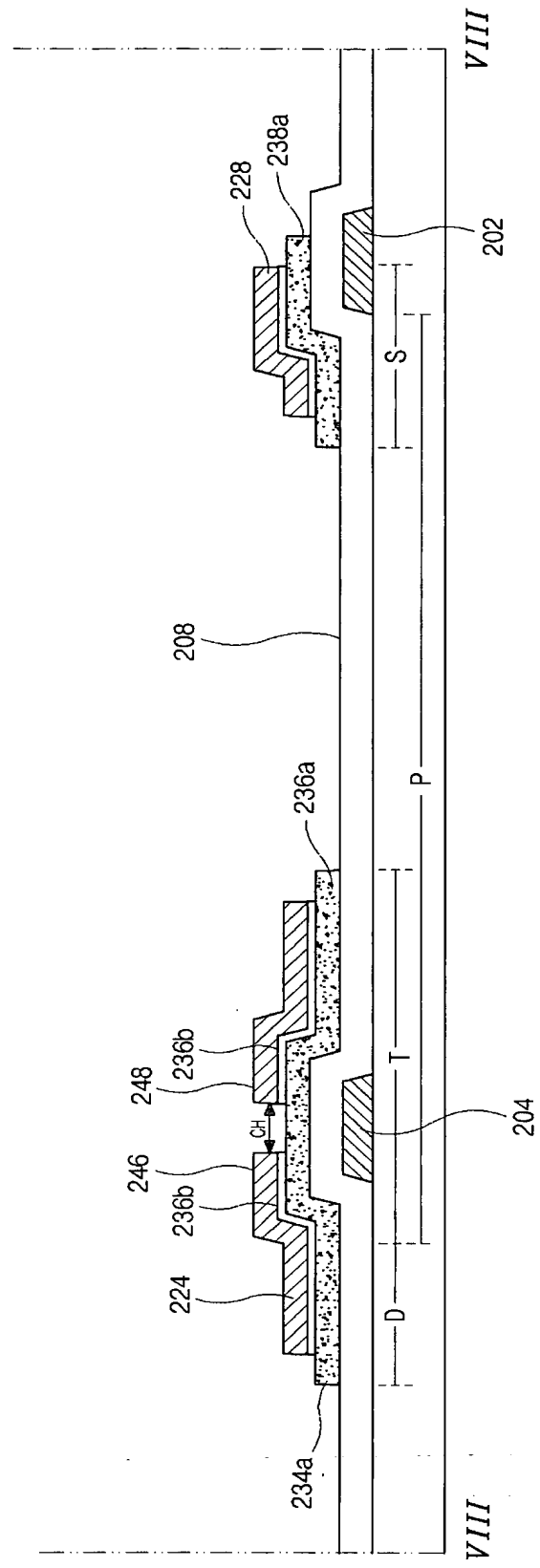


FIG. 8G

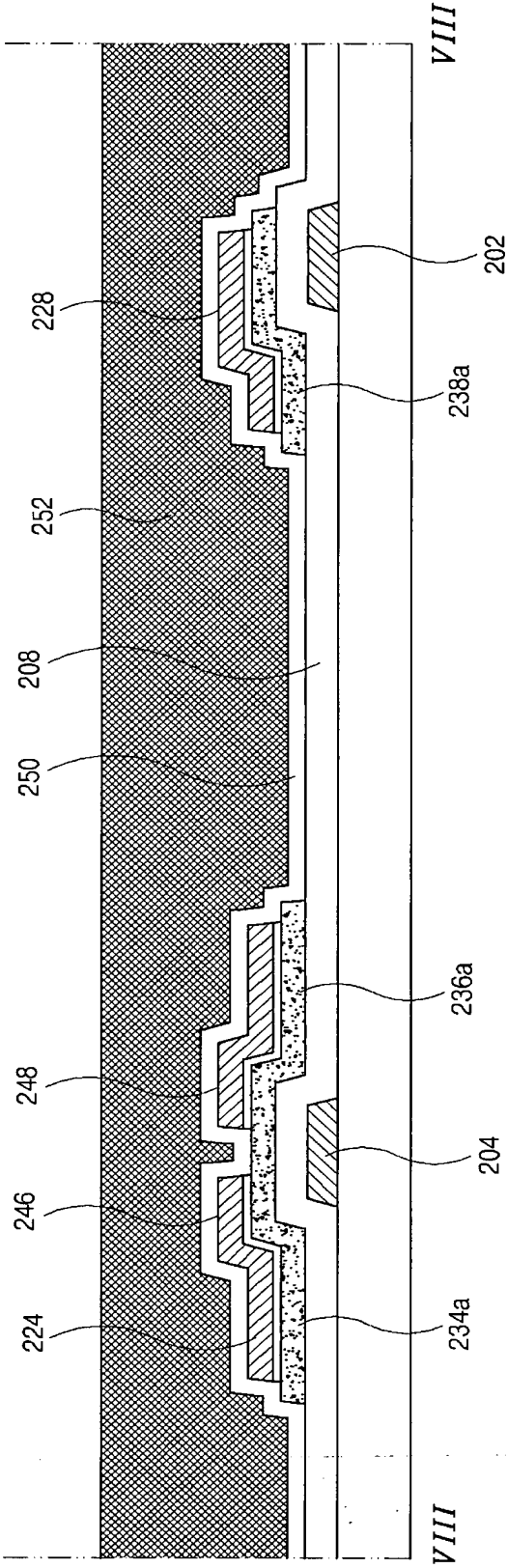


FIG. 8H

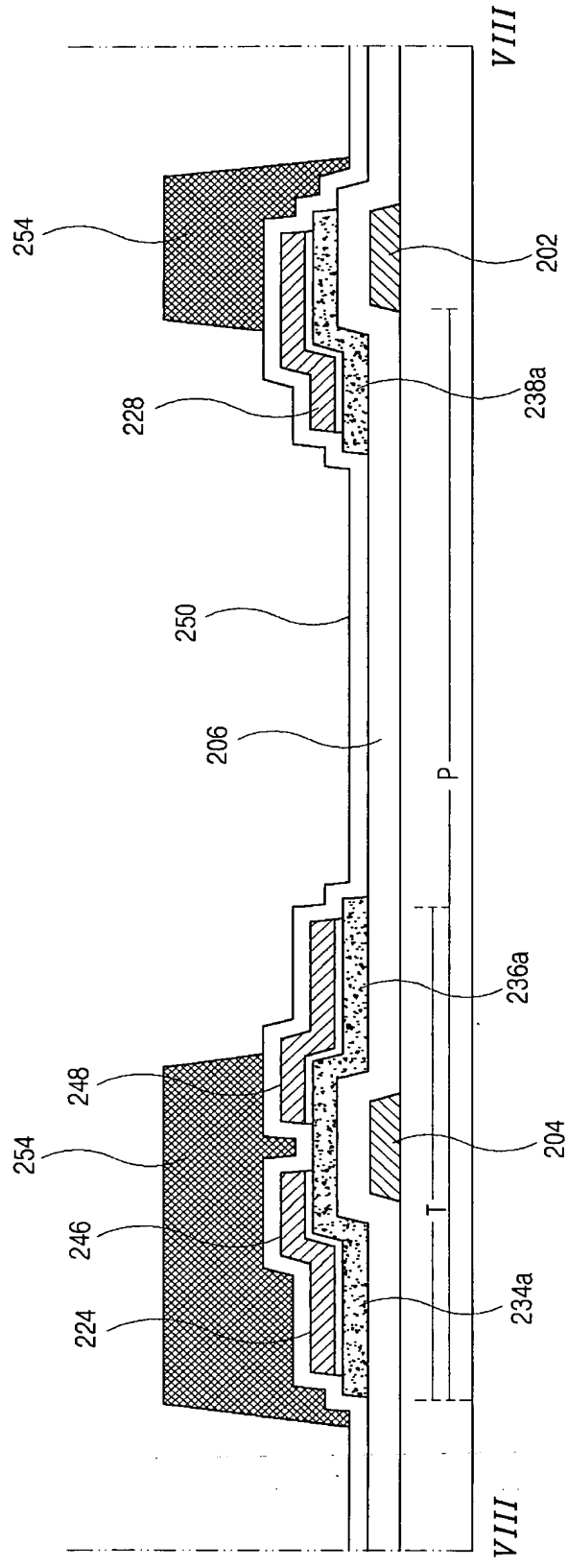


FIG. 8I

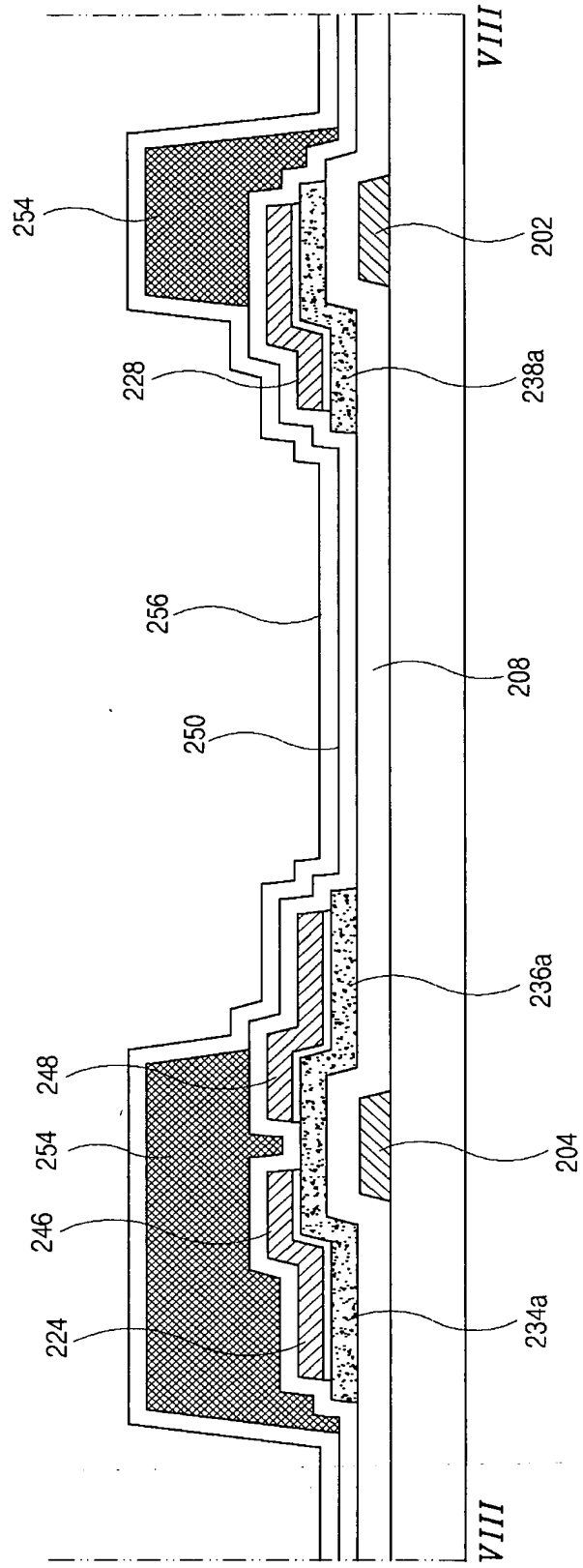


FIG. 8J

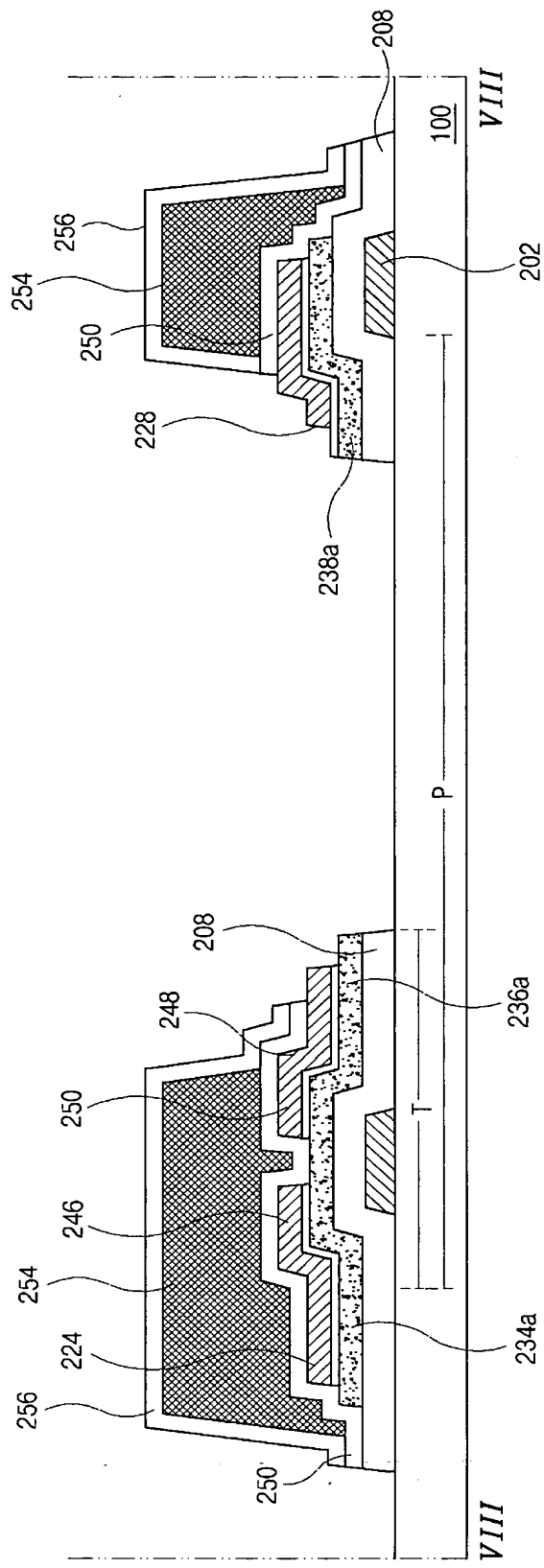


FIG. 8K

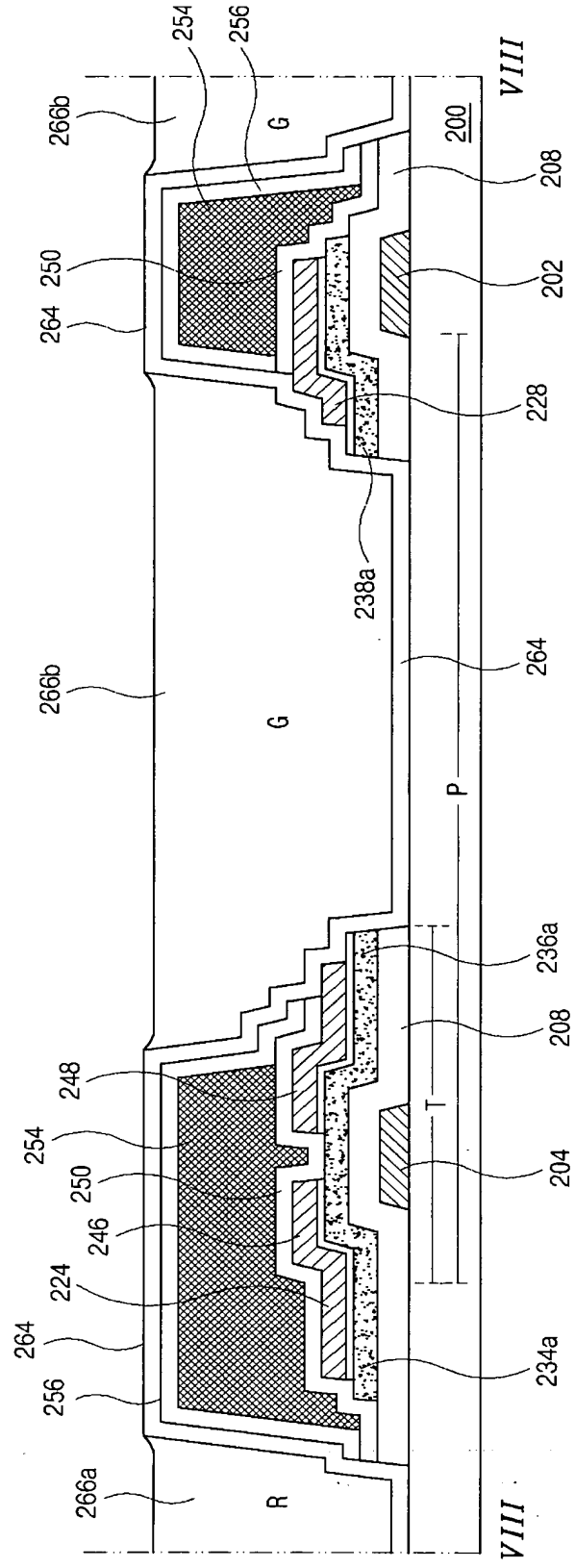


FIG. 8L

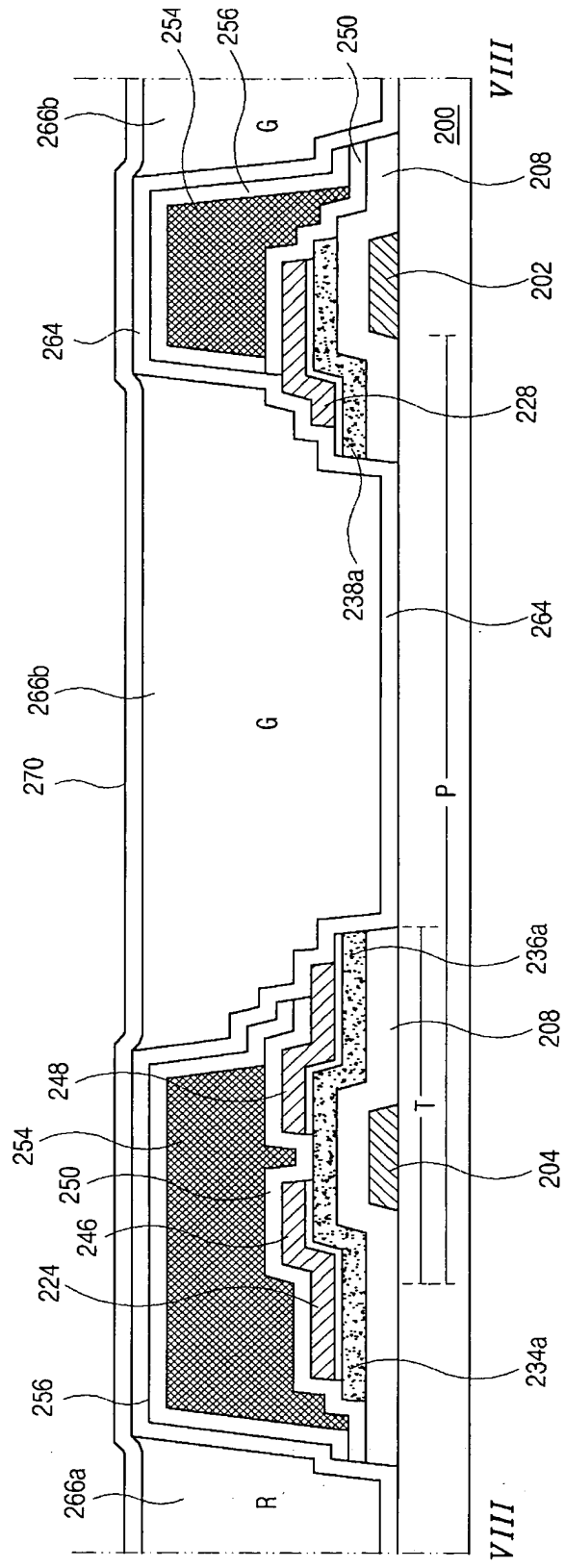


FIG. 8M

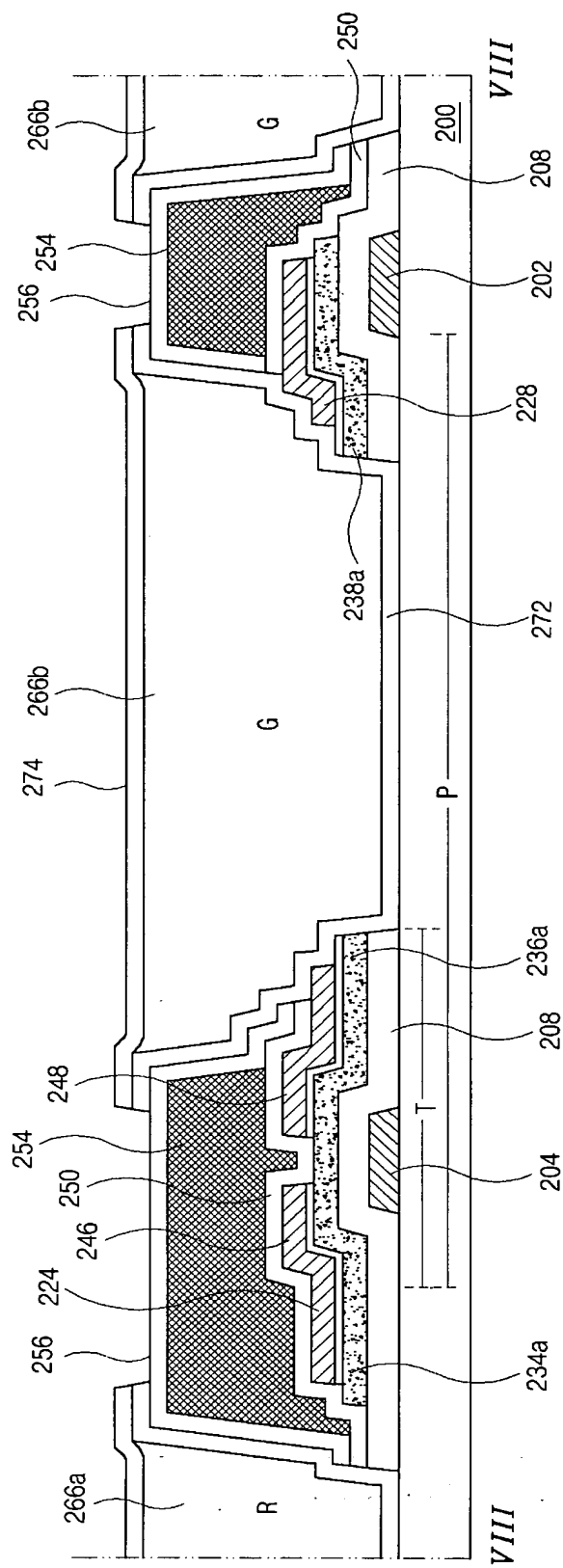


FIG. 9A

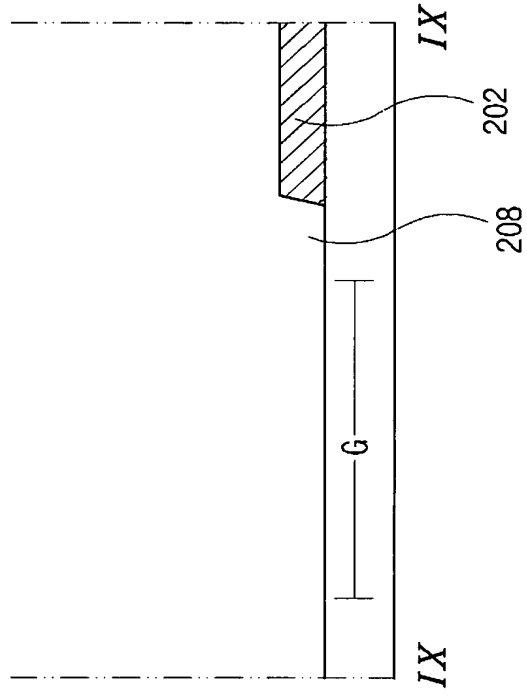


FIG. 9B

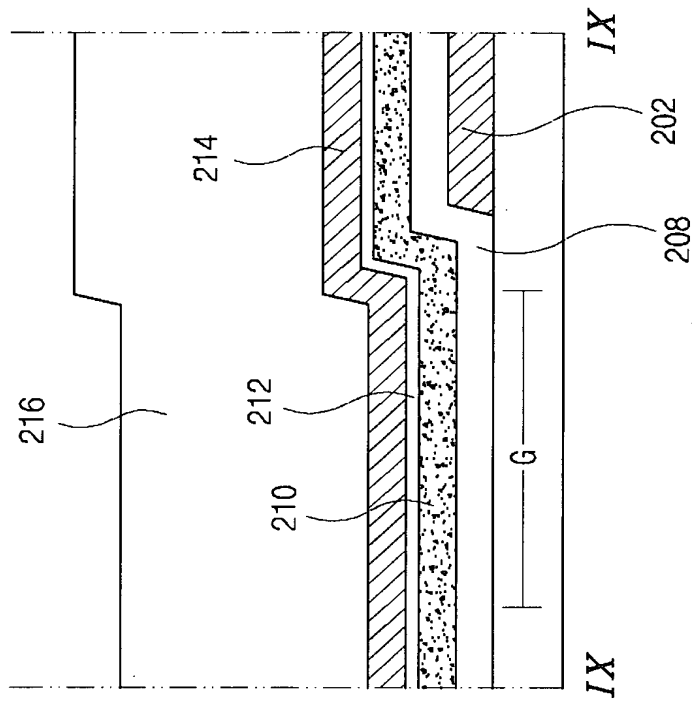
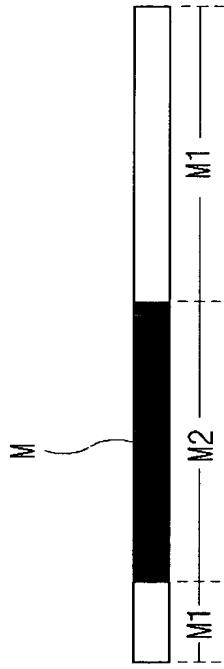


FIG. 9C

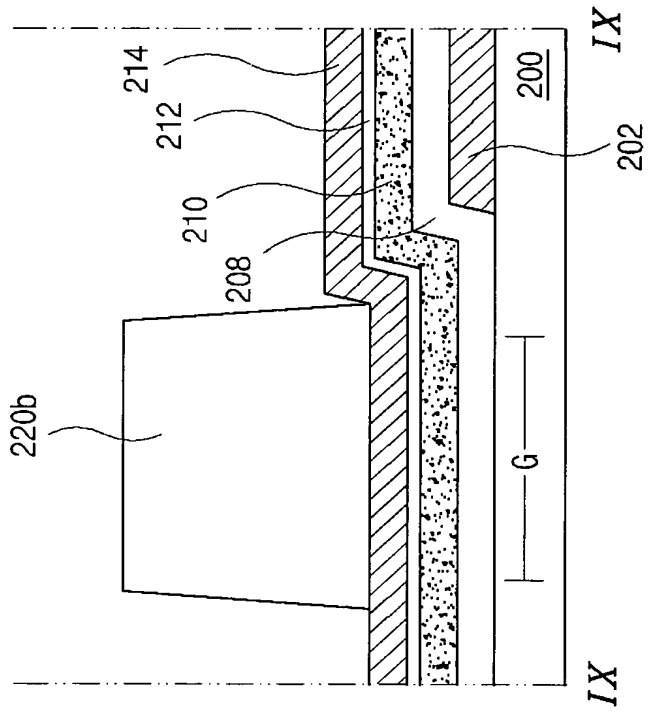


FIG. 9D

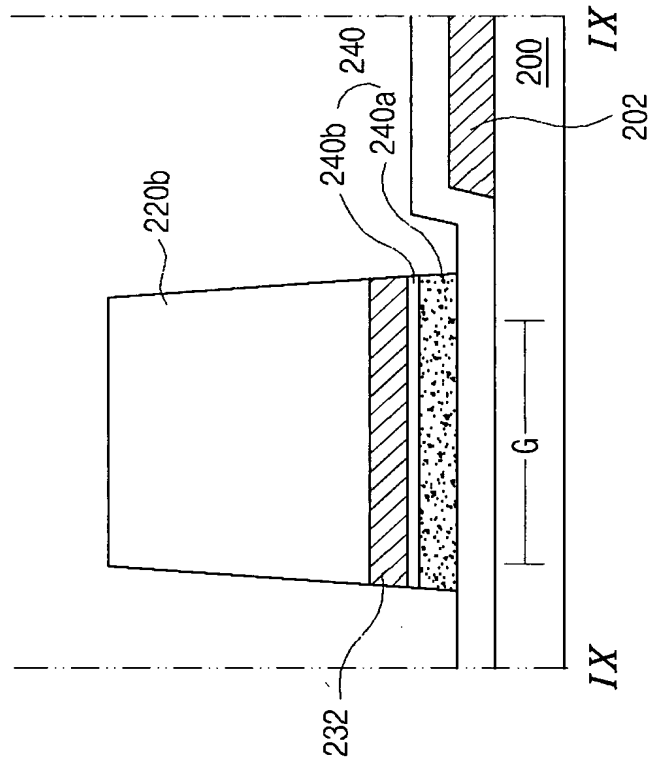


FIG. 9E

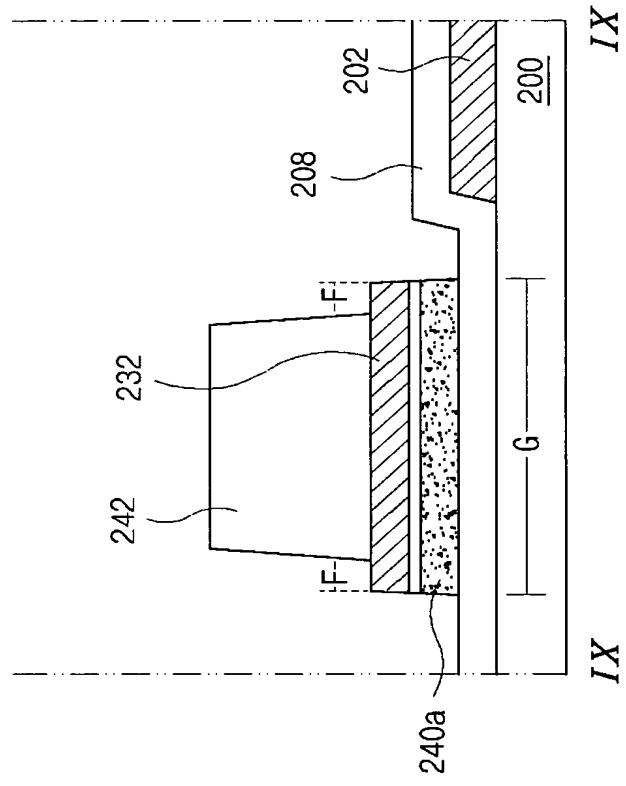


FIG. 9F

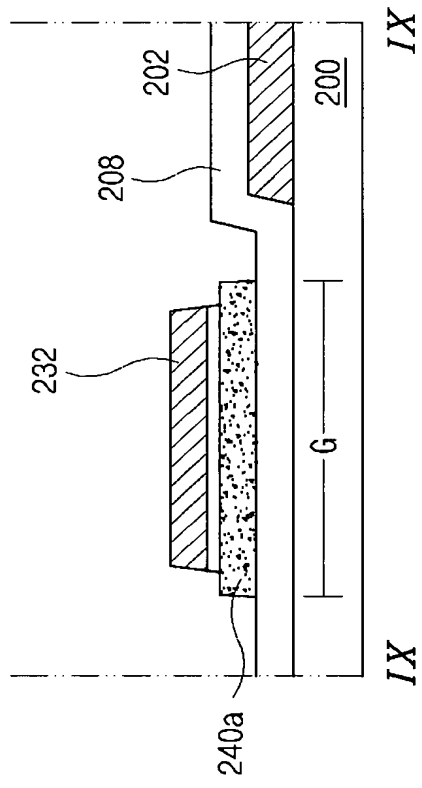


FIG. 9H

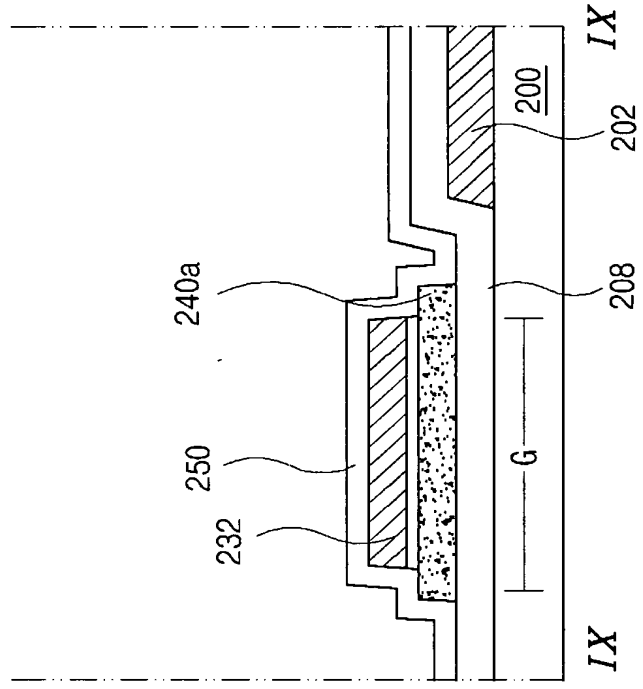


FIG. 9I

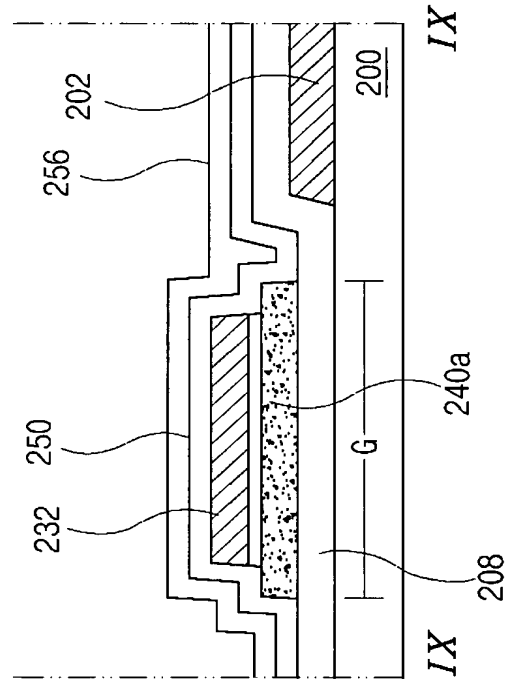


FIG. 9J

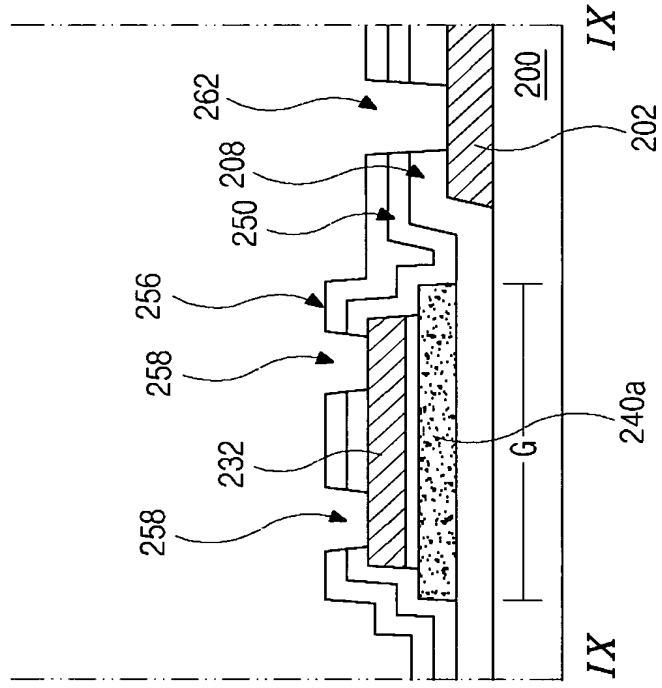


FIG. 9K

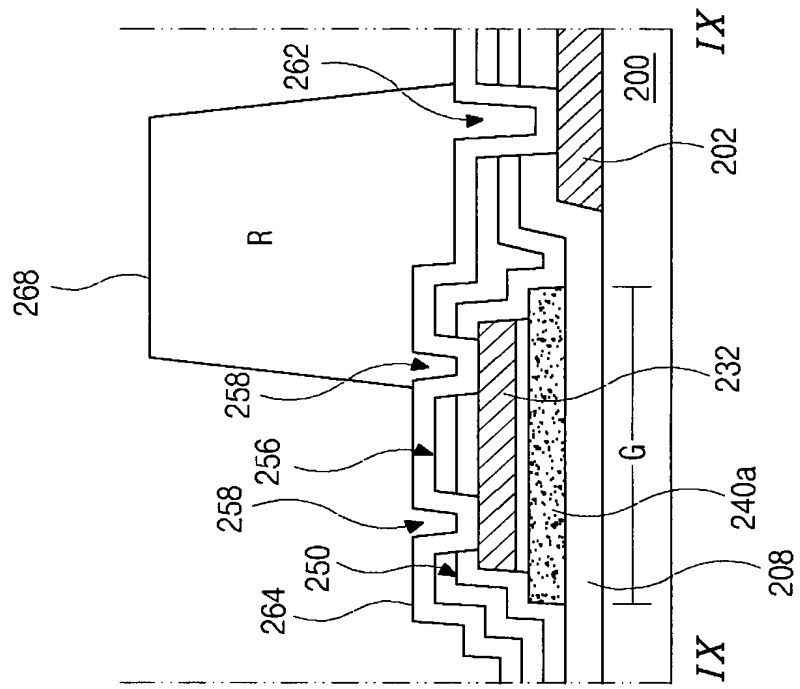


FIG. 9M

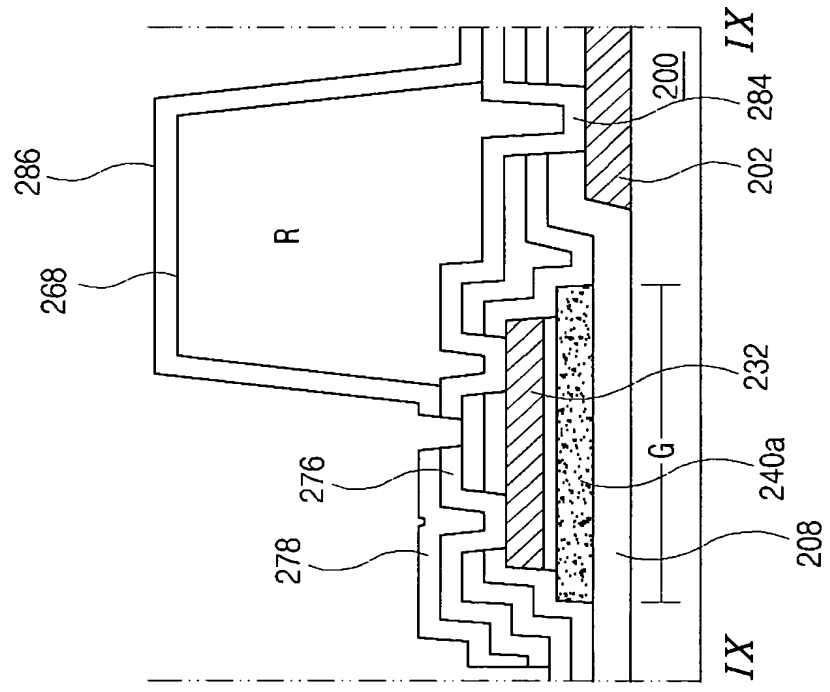


FIG. 10A

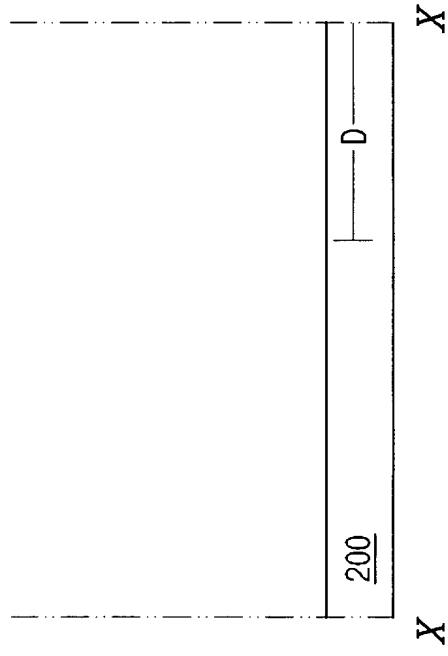


FIG. 10B

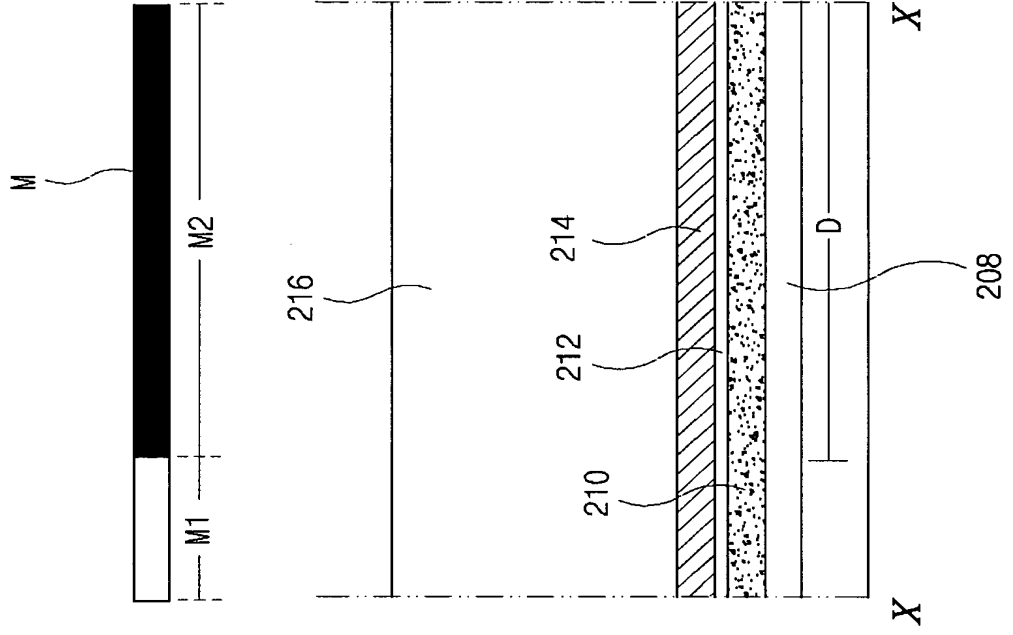


FIG. 10C

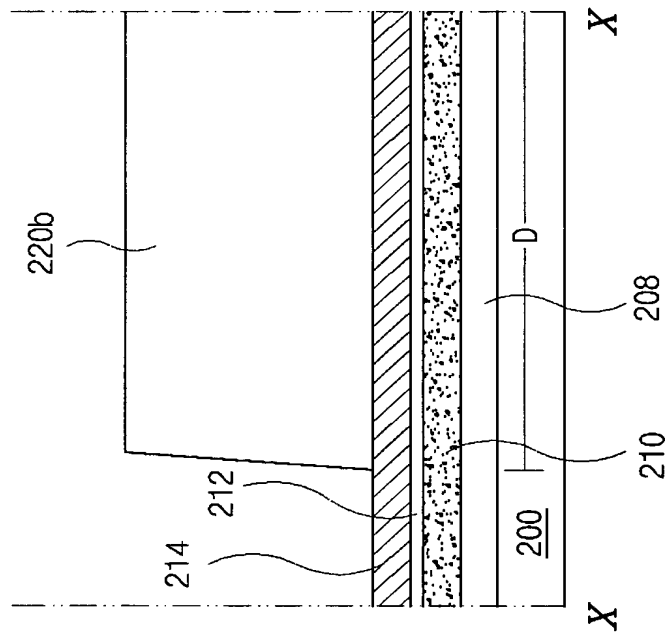


FIG. 10D

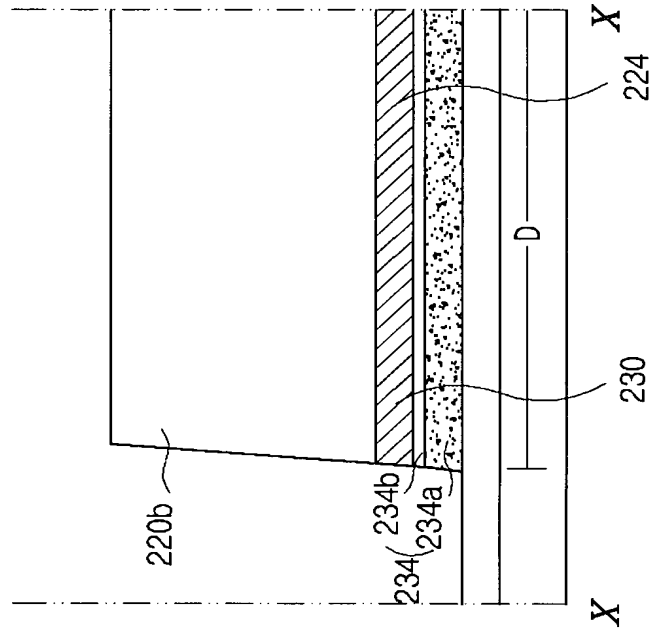


FIG. 10E

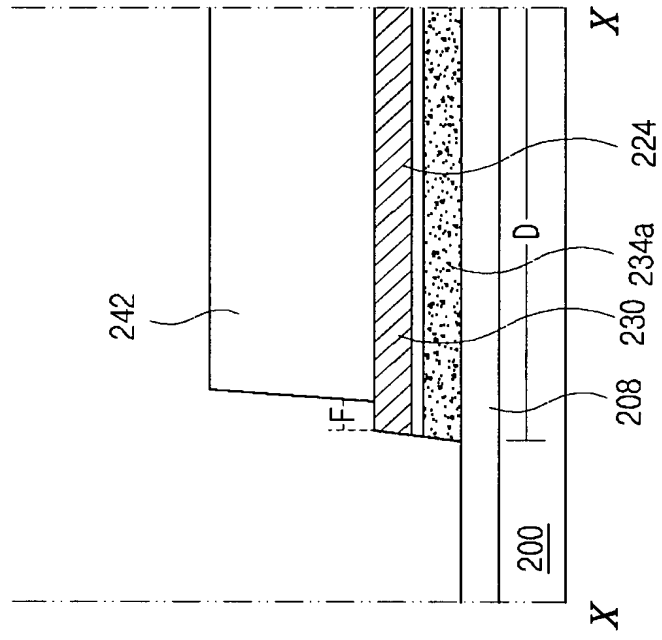


FIG. 10F

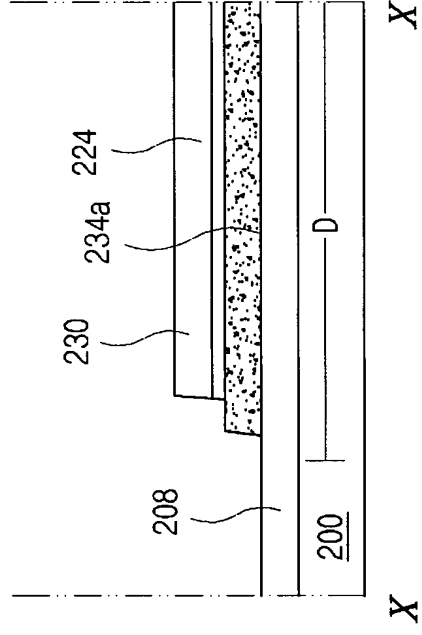


FIG. 10G

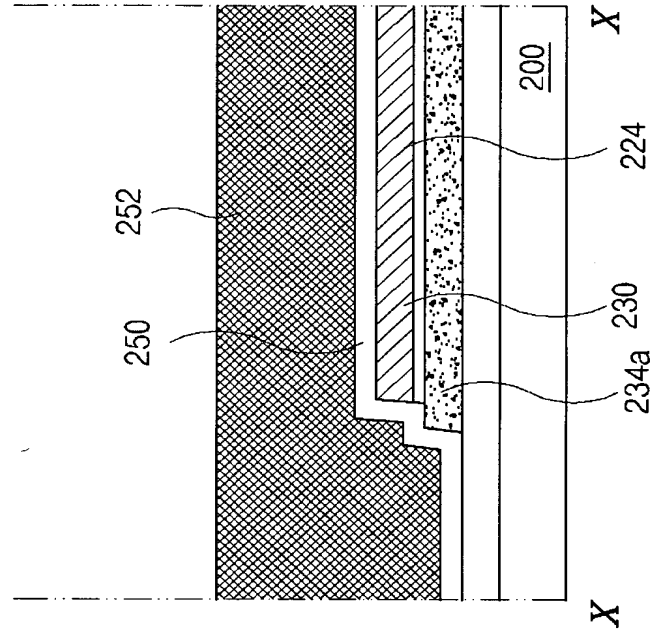


FIG. 10H

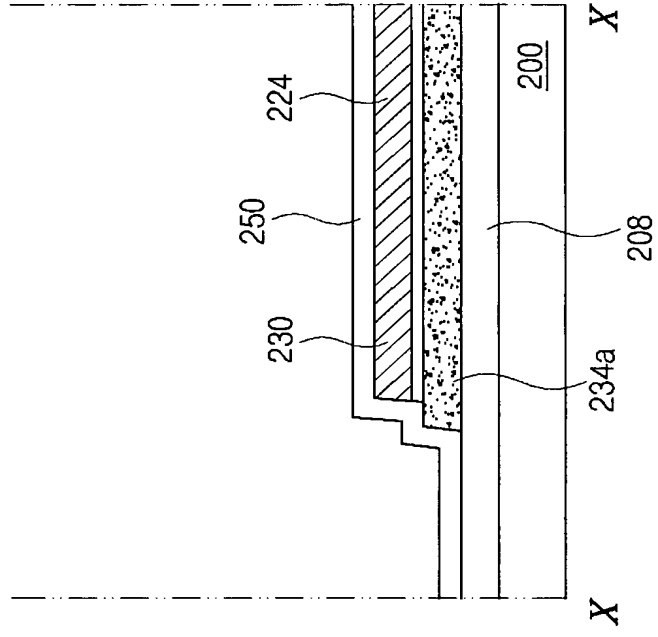


FIG. 10I

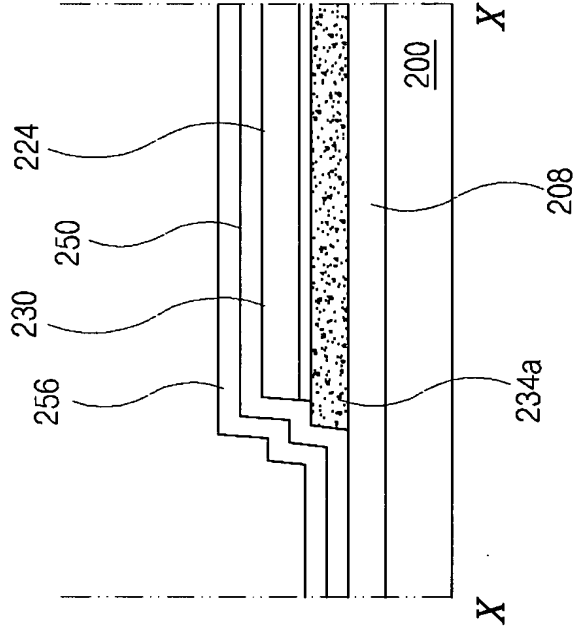


FIG. 10J

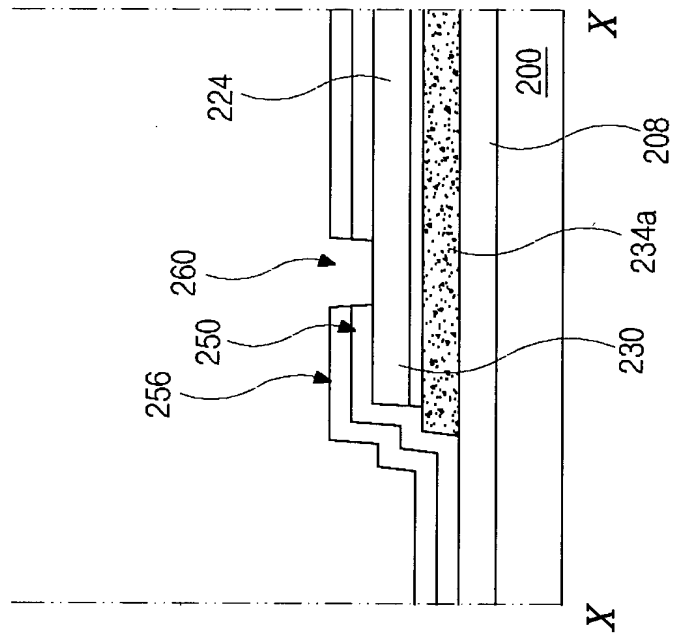


FIG. 10L

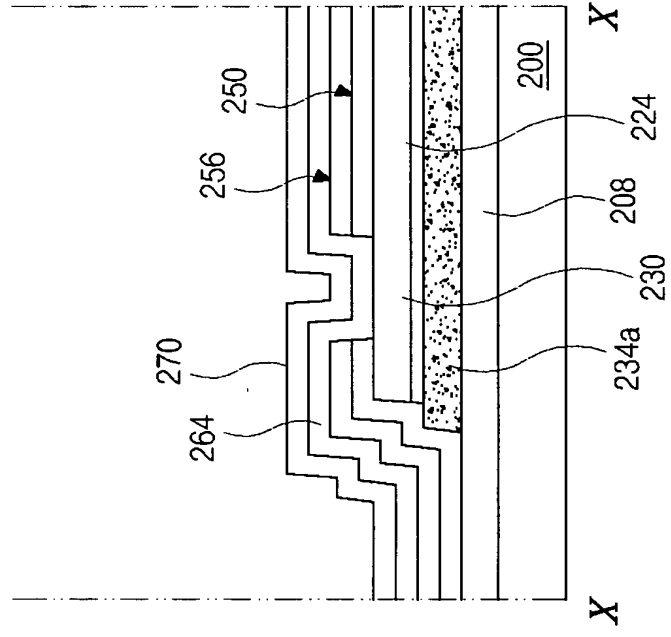


FIG. 12

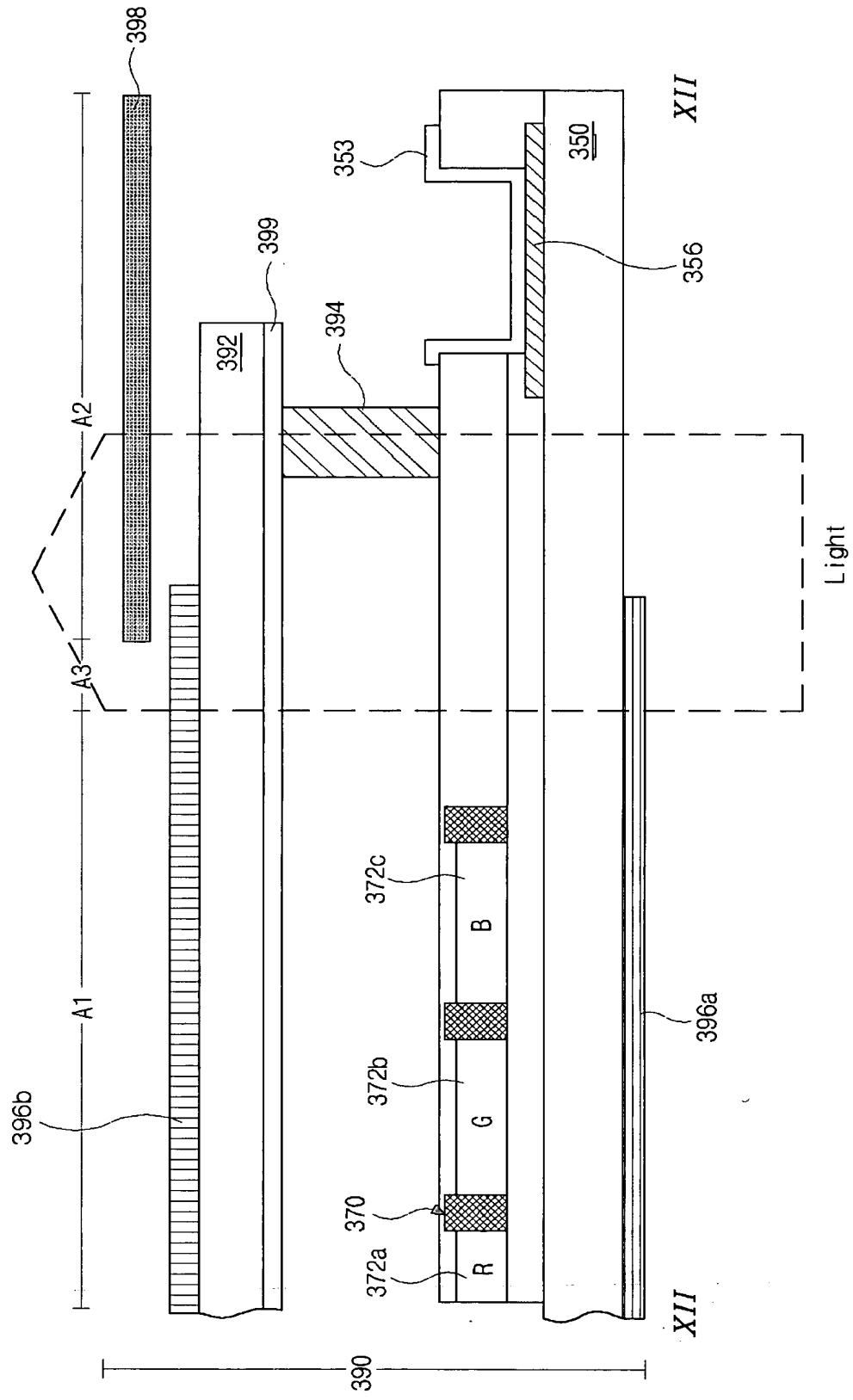


FIG. 13

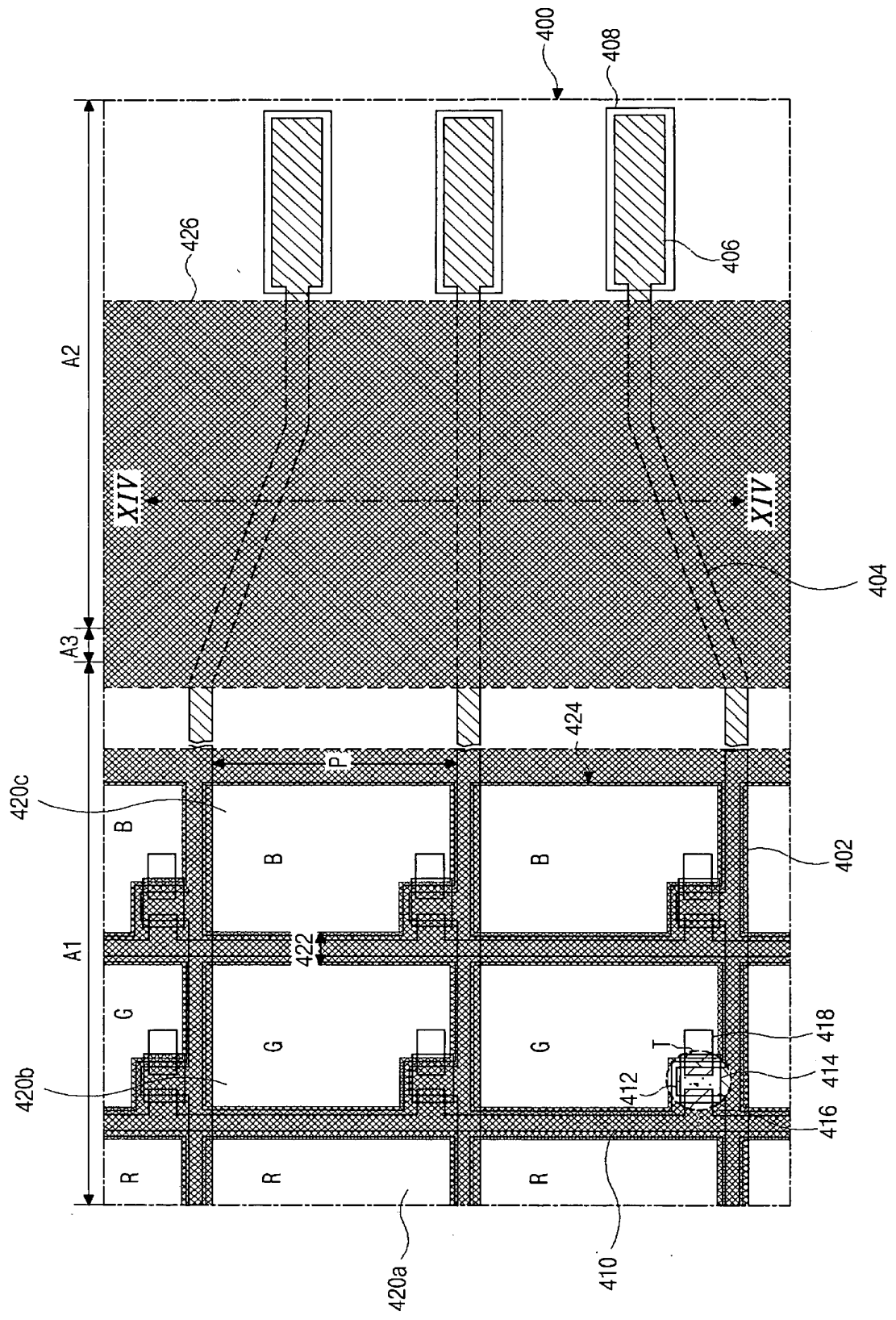


FIG. 14A

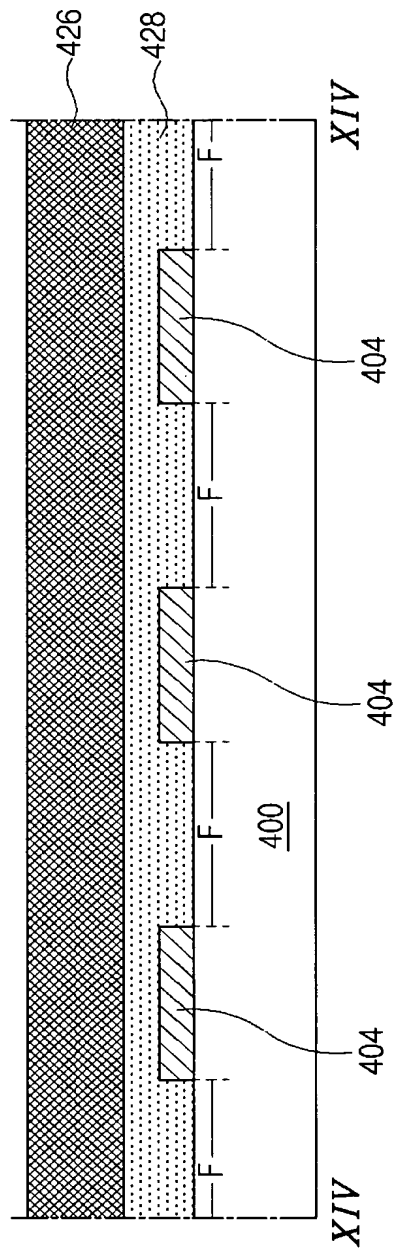
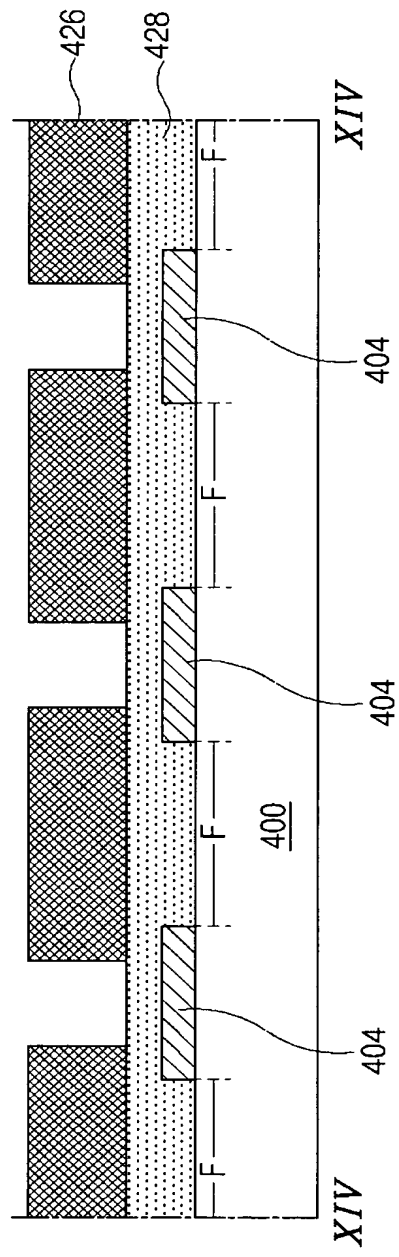


FIG. 14B



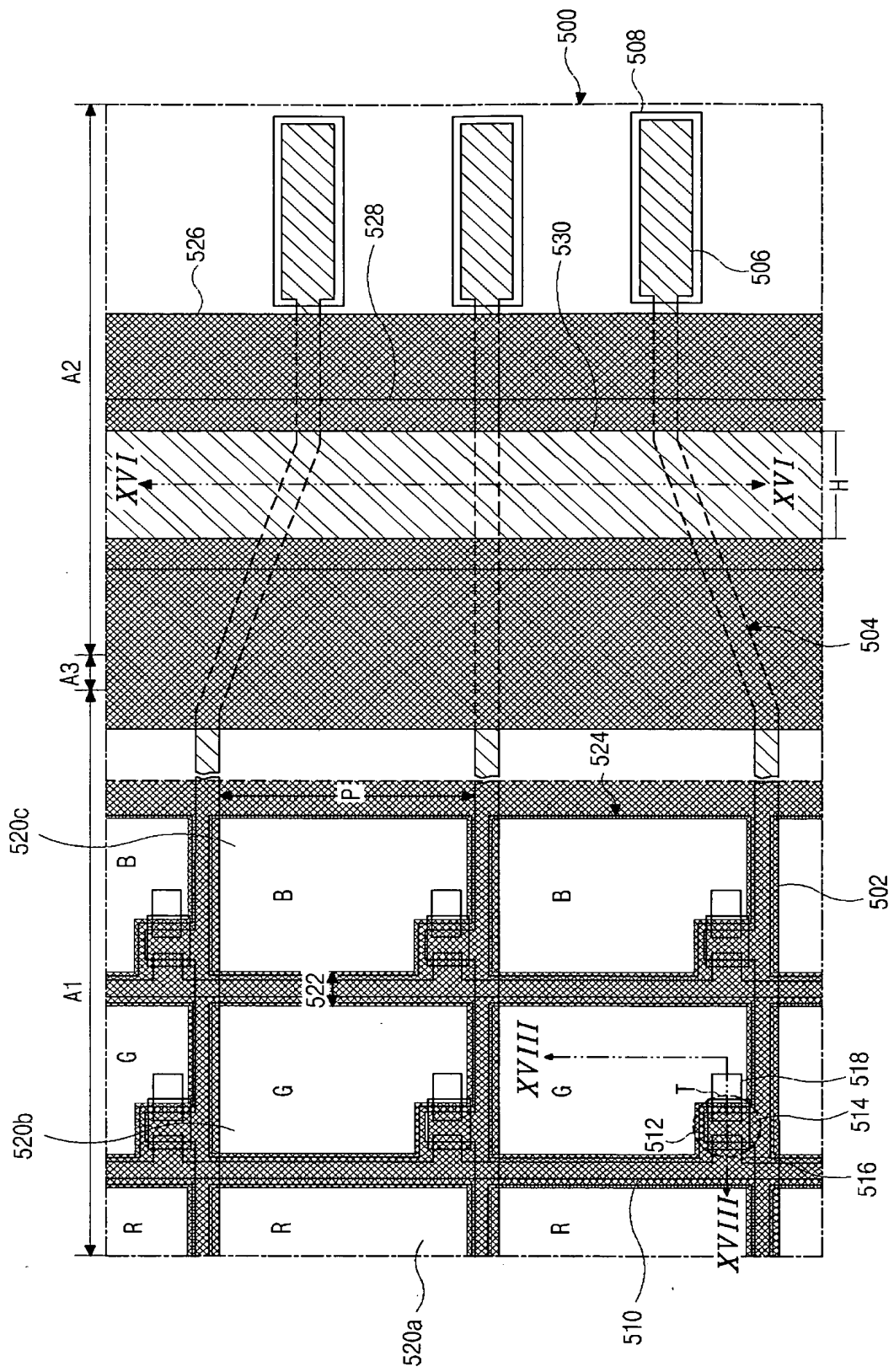
[illegible]

FIG. 16A

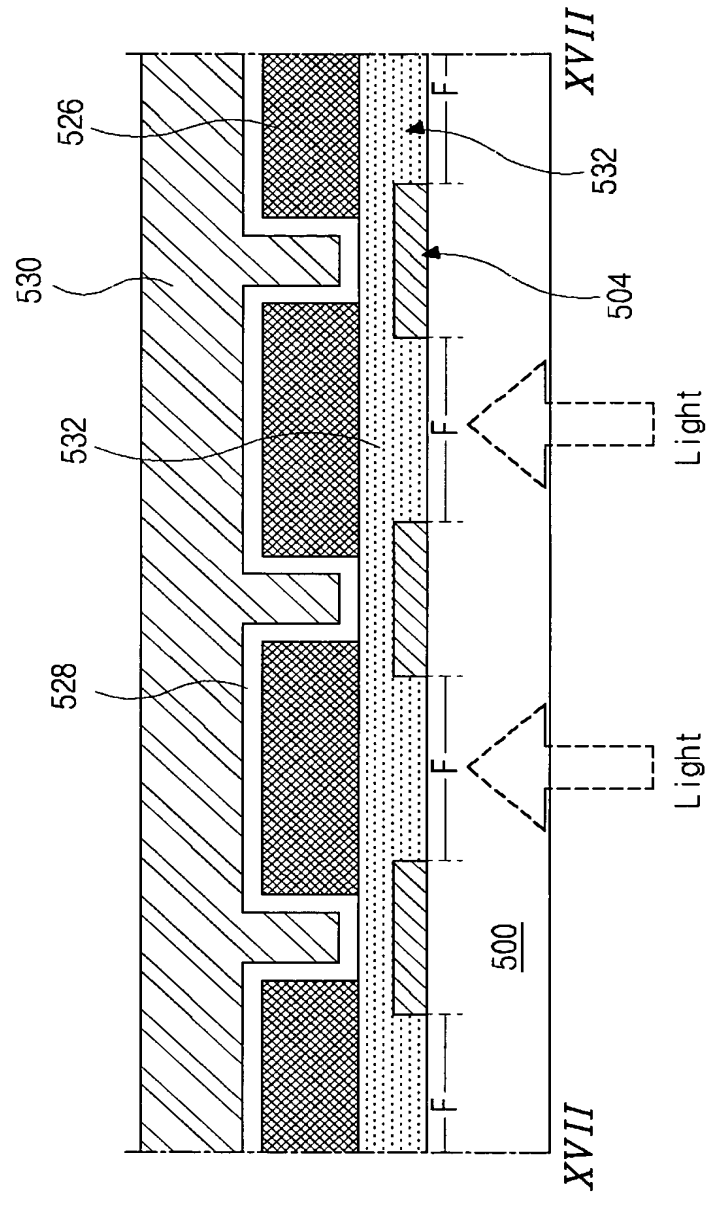


FIG. 16B

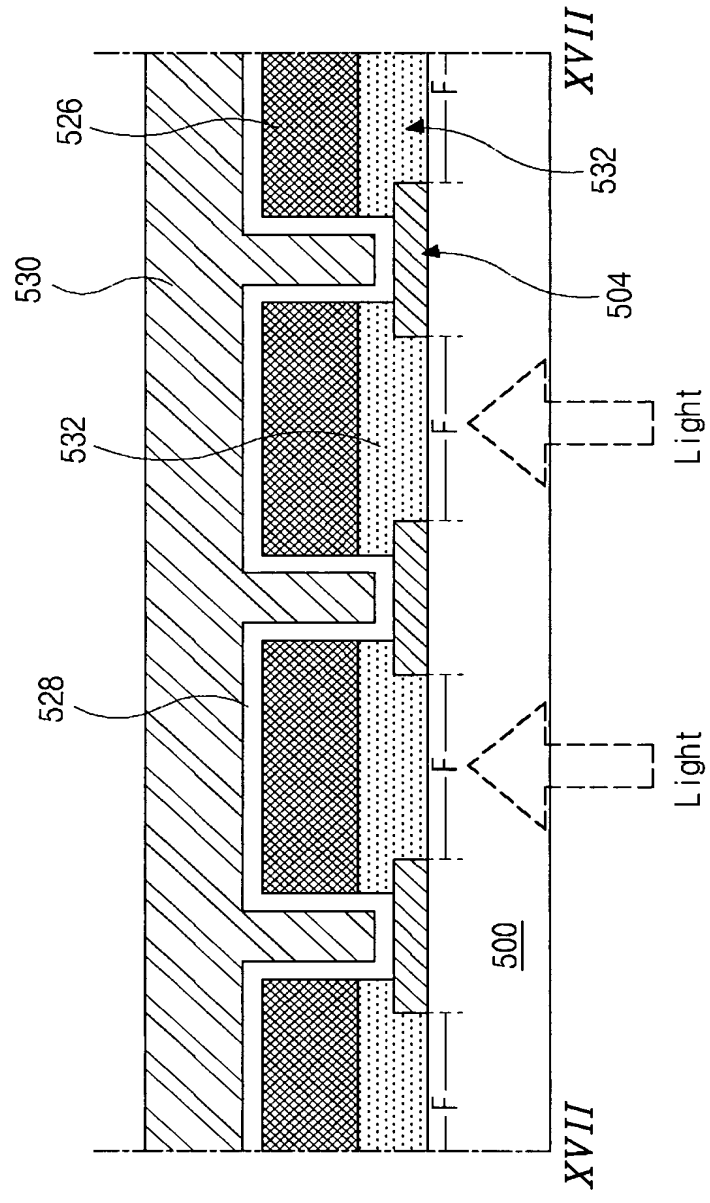


FIG. 17

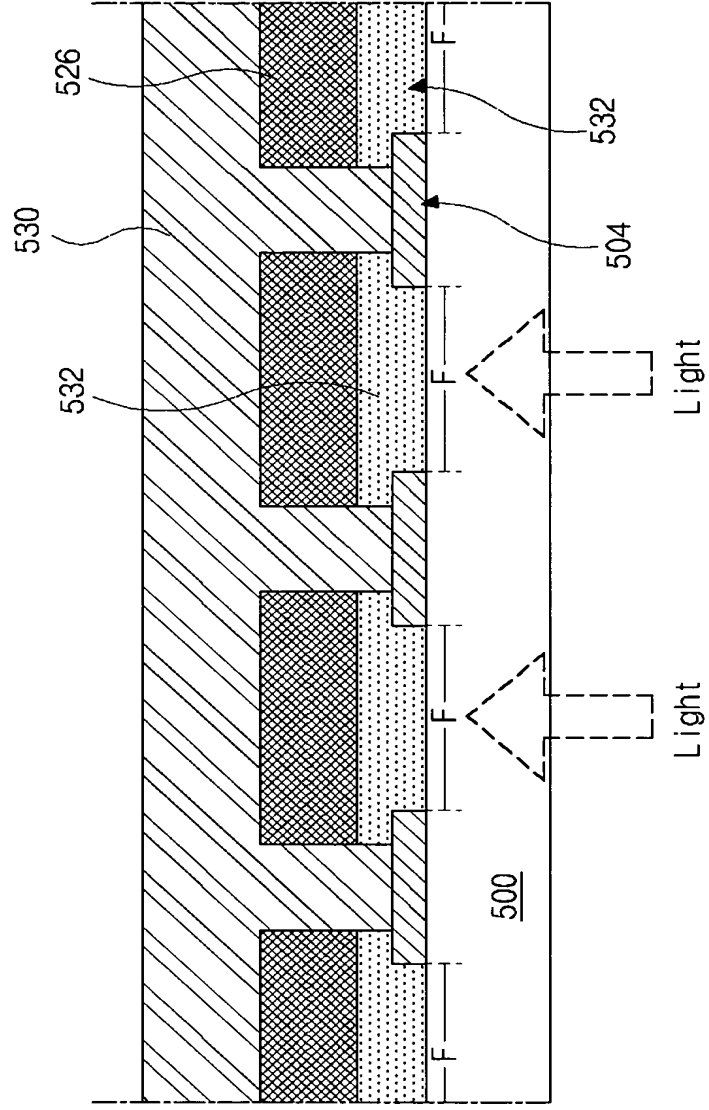


FIG. 18B

